

**DESIGN OF ZIGBEE TRANSMITTER FOR IEEE
802.15.4 STANDARD**

A THESIS SUBMITTED IN PARTIAL FULFILMENT OF THE
REQUIRMENTS FOR THE
DEGREE OF

**MASTER OF TECHNOLOGY
IN
VLSI DESIGN AND EMBEDDED SYSTEMS**

By

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Roll No: 209EC2131



DEPARTMENT OF ELECTRONICS AND COMMUNICATION
ENGINEERING

NATIONAL INSTITUTE OF TECHNOLOGY

ROURKELA, ODISHA

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UNDER THE GUIDANCE OF

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ROURKELA

CERTIFICATE

This is to certify that the thesis entitled, “**DESIGN OF ZIGBEE TRANSMITTER FOR IEEE 802.15.4 STANDRAD**” submitted by **JOSHNA PALEPU Roll no: 209EC2131** in partial fulfilment of the requirements for the award of Master of Technology Degree in **Electronics & Communication Engineering** with specialization in **VLSI Design and Embedded Systems** during 2010-2011 at the National Institute of Technology, Rourkela (Deemed University) is an authentic work carried out by her under my supervision and guidance. To the best of my knowledge, the matter embodied in the thesis has not been submitted to any other University / Institute for the award of any Degree or Diploma.

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Abstract

ZigBee is a standard defines a set of communication protocols for low-data-rate short-range wireless networking. ZigBee-based wireless devices operate in 868 MHz, 915 MHz, and 2.4 GHz frequency bands. The maximum data rate is 250 K bits per second. ZigBee is mainly for battery-powered applications where low data rate, low cost, and long battery life are main requirements. This thesis explores low power RFIC design for various blocks in Zigbee Transmitter.

Zigbee RFTransmitter Comprises of Low Pass Filter, Variable Gain Amplifier, Up conversion Mixer and Power Amplifier.

The proposed VGA is characterized by a wide range of gain variation The single-stage VGA is designed in UMC 0.18- μ m CMOS technology and shows the maximum gain variation of 62 dB. The VGA dissipates 630 μ A from 1.8-V supply while occupying (250 μ m x 167.3 μ m) of chip area.

A low-voltage low-power and high linearity up-conversion mixer, designed in UMC 0.18- μ m RFCMOS technology is proposed to realize the transmitter front-end in the frequency band of 2.45 GHz. The proposed mixer can convert a 5 MHz intermediate frequency (IF) signals to a 2.45GHz RF signals, with a local oscillator at 2.45GHz. Simulation results demonstrate that at 2.45GHz, the circuit provides -11.30dB of conversion gain and the input-referred third-order intercept point (IIP3) of 35.16 dBm, output-referred third order intercept point(OIP3) of 12.88 dBm while drawing only 10mA for the mixer core under a supply voltage of 1.8 V.

A low power Differential class A power amplifier is designed in the UMC 0.18 μ m RFCMOS technology. The class A power amplifier provides 0 dBm output power with a power-added efficiency (PAE) of 22% and Power Gain of 10dB with 1.8V supply voltage. The dc power consumption is only 4.5mW.

And all these blocks were integrated and simulated using Cadence© SpectreRF simulator in UMC-0.18 μ m Mixed Signal CMOS RF models for the best simulation results.

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Chapter-1

Introduction

Introduction

In past decades, the tremendous growth in wireless communication systems has given push to the development of low power radio frequency integrated circuits (RFICs). Power consumption of a RFIC design has become a major concern due to battery lifetime consideration. Therefore, a single battery solution becomes very attractive for commercial and industrial purposes.

In recent years, down-scaling in CMOS advanced technologies has provided high performance in digital circuits and inexpensive cost to meet the increasing demand of wireless communication products. With this technology advancement, the unity-current gain frequency (f_T) of CMOS technology is now over several tens of GHz and this makes the realization of system-on-chip solution possible to further reduce the cost. The demand of highly integrated CMOS RF building blocks with low power consumption has driven our research initiatives to explore an area of low power CMOS RFIC designs for applications in a RF front-end transceiver [1].

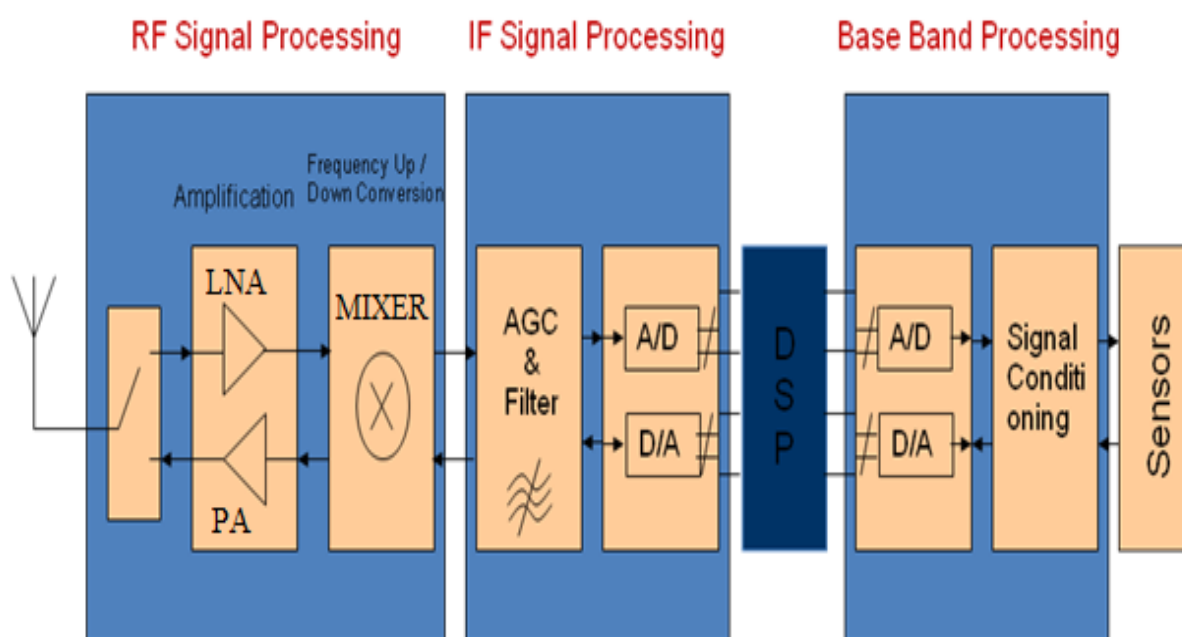


Figure 1.1 Simplified Block Diagram of Radio Frequency Transceiver

A transceiver is a system that transmits or receives a signal. Figure 1.1 shows a simplified block diagram of a radio frequency (RF) transceiver. The transceiver can be split into the RF front-end part that performs the transmission and reception of signals and the digital part that takes care of the signal processing functions. In general, the RF front-end part is the most power hungry portion of a transceiver. If we can reduce the power consumption of the front-end part, it will be a significant achievement to minimize the power consumption of the transceiver. As a result, the overall power consumption of the wireless device can also be reduced. Therefore, the goal of this thesis is to explore the low voltage design issues in the RF front-end part of a transceiver [2].

1.1 Research Goal

There are several major RF building blocks in a front-end transceiver. This thesis concentrates on the design of a low-voltage CMOS up conversion mixer and a Class A Power Amplifier in the transmitting path of the RF front-end section in a transceiver.

A Variable Gain Amplifier is designed such that it stabilizes the amplitude of the output signal under various conditions and supplies a constant-amplitude signal to the detector and filter sections of the read channel.

With the access to UMC 0.18- μm CMOS technology up-conversion mixer is designed to operate at 1.8V supply. The mixer performance is characterized and the measurement results are simulated using SpectreRF simulator in Cadence.

The third objective is to investigate a Class A Power Amplifier. Power amplifiers are typically the most power hungry building block of RF Transceiver. The Power Amplifier is designed to operate at 1.8V voltage supply with Operating frequency of 2.45GHz. The analysis of the performance is verified through simulation using SpectreRF simulator in Cadence.

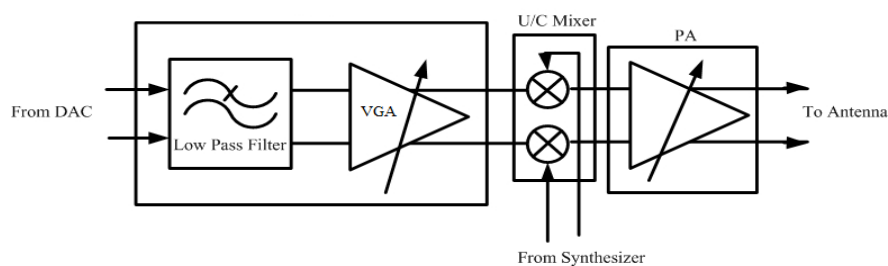


Figure 1.2 Transmitter Block Diagram

1.2 Thesis outline

This thesis is divided into seven chapters. It is organized in such way as to properly layout the detail investigations and results of the research work.

The motivation and research goal are presented in Chapter 1 with a summary of the thesis outline.

Chapter 2 is an overview on modern radio receivers. A general background on different types of receiver architectures are presented. The state-of-the-art of these architectures is reviewed.

Chapter 3 provides a background theory review of the variable gain amplifier and the circuit design details of variable gain amplifier and concluded with the post layout simulations.

Chapter 4 provides a background theory review of the up-conversion mixer operation. The fundamentals and parameters of performance are discussed and followed by the circuit design details of mixer .The chapter is concluded with simulation results.

Chapter 5 starts with a background theory review of the Power amplifier and their classifications followed by the circuit design description of the Class A power amplifier. Simulation results of class A power amplifier are provided to verify the performance analysis. This chapter concluded with the post layout simulation of Class A power amplifier

Chapter 6 starts with the design of the zigbee transmitter and concludes with the simulation results.

Conclusion and future work of this thesis are presented in Chapter 7.

Chapter-2

Radio Transceiver Architectures

2.1 Radio Transceiver Architectures

Primary criteria in selecting Transceiver Architectures [3]:

- Complexity
- Cost
- Power dissipation
- No. of external components

The first consideration in designing an RFIC is the system architecture and its frequency plan. Architecture is determined by choosing among different possible ones:

- Superheterodyne using one or several IF stages
- **Direct conversion**
- Low IF

By frequency plan, it means the intermediate frequency/frequencies choice (Not Applicable for direct conversion architecture), with considerations on image interference avoidance, blockers, and RF leakage/isolation analysis, DC-offset issue, I/Q imbalance issue, etc. Frequency plan specification impacts on system noise, interference, and distortion analysis. In a generalized sense, special issues associated with chosen RF transceiver architecture are addressed in frequency plan specification.

For direct conversion, the following issues are important:

- DC offset or order-two products
- 1/f or flicker noise
- I/Q imbalance impacts
- etc.

2.1.1 Superheterodyne receiver

Superheterodyne receiver uses frequency mixing or heterodyning to convert a received signal to a fixed intermediate frequency, which can be more conveniently processed than the original radio carrier frequency.

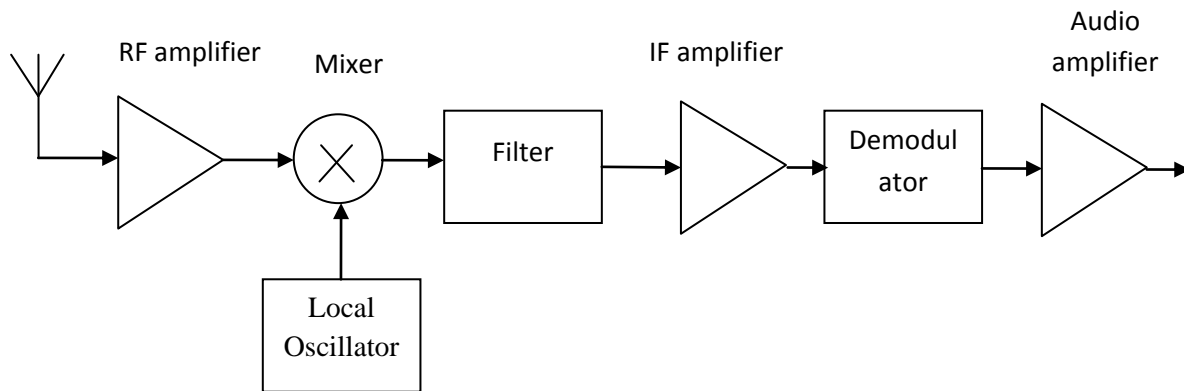


Figure 2.1 Block Diagram of Superheterodyne Receiver

The principle of operation of the superheterodyne receiver depends on the use of frequency mixing or heterodyning. The signal from the antenna is filtered sufficiently at least to reject the image frequency and possibly amplified. A local oscillator in the receiver produces a sine wave which mixes with that signal, shifting it to a specific intermediate frequency (IF), usually a lower frequency. The IF signal is itself filtered and amplified and possibly processed in additional ways. The demodulator uses the IF signal rather than the original radio frequency to recreate a copy of the original modulation (such as audio).

The Figure 2.1 shows the minimum requirements for a single-conversion superheterodyne receiver design. The following elements are common to all superheterodyne circuits: a receiving antenna, a tuned stage which may optionally contain amplification (RF amplifier), a variable frequency local oscillator, a frequency mixer, a band pass filter and intermediate frequency (IF) amplifier, and a demodulator plus additional circuitry to amplify or process the original audio signal.

The advantages of heterodyne scheme are

- Good overall performance.
- Flexibility in frequency planning.
- No DC offset problem.
- Inphase and quadrature matching is superior.

The disadvantages of superheterodyne receiver are

- Requires external components.
- It suffers from image problems.
- Higher power consumption.
- High implementation results.
- Difficulties in multimode transceivers.

Due to high power consumption and high implementation costs, this superheterodyne is not suitable for IEEE 802.15.4.

2.1.2 Low IF receiver

In a low-IF receiver, the RF signal is mixed down to a non-zero low or moderate intermediate frequency, typically a few megahertz.

It combines the advantages of both heterodyne and direct conversion scheme.

The advantages of this receiver are

- Avoids DC offset problem.
- Eliminate IF SAW filter, PLL and image filtering.

The disadvantage of this scheme is that it suffers impairments such as even order nonlinearities, local oscillator pulling and local oscillator leakage.

Mainly, the low IF scheme requires stringent image rejection as an adjacent channel becomes its image. Image rejection in low IF can be achieved either in analog or digital domain. In analog domain, we can reduce this image frequency by using complex band pass filters. By the use of this band pass filters chip size and power consumption will increase. Also it requires a second low frequency digital mixer. In digital domain, the chip size will not increase. The disadvantage in digital domain solution is it requires good inphase and quadrature phase matching. Also signal bandwidth in low IF is two times that of direct conversion, so ADC sampling rate will be doubled and hence power consumption will be higher. Another disadvantage is design complexity also increases.

2.1.3 Direct Conversion receiver

The direct conversion receiver converts the carrier of the desired channel to the zero frequency immediately in the first mixers. Hence the direct conversion is often called also as

a zero IF receiver, or a homodyne receiver if the LO is coherently synchronised with the incoming carrier. The synchronization of the LO directly to the RF carrier can be avoided with other techniques in current applications used mostly in optical reception.

Homodyne receivers translates the channel of interest directly from RF to baseband ($\omega_{IF}=0$) in a single stage. Hence these architectures are called Direct IF architectures or Zero-IF architectures. For frequency and phase modulated signals, down conversion must provide quadrature outputs so as to avoid loss of information. It translates the RF signal directly to the baseband signal.

The block diagram of direct conversion receiver is shown in the Figure 2.2 below. Two direct conversion mixers must be used for demodulation already at RF if a signal with Quadrature modulation is received. Otherwise, a single sideband signal with suppressed carrier containing quadrature information, like QPSK, would alias its own independent single sideband channels in quadrature over each other. Hence, the RF mixers are already a part of the demodulator although several other processing steps are performed before the detection of bits. This is also a distinct benefit of the direct conversion scheme. Because the information at the both sides of the carrier comes from the same source having an equal power. Hence the image power is always the same with the desired signal and the quadrature accuracy requirements are only moderate. Thus the required image rejection is realizable with IC technologies even at high frequencies.

A low pass filter with a bandwidth of half the symbol rate is suitable for the channel selection. This gives a noise advantages over other architectures and also image noise filtering is needed between the LNA and mixers. The external components in the signal path are now limited to the pre-selection filter at the input. Hence only the input of LNA must be matched in order to maintain the filter response unchanged. The interfaces between other blocks can be optimized during the design independently to optimize the performance with respect to noise, linearity and power. Of course, flexibility also increases the design complexity.

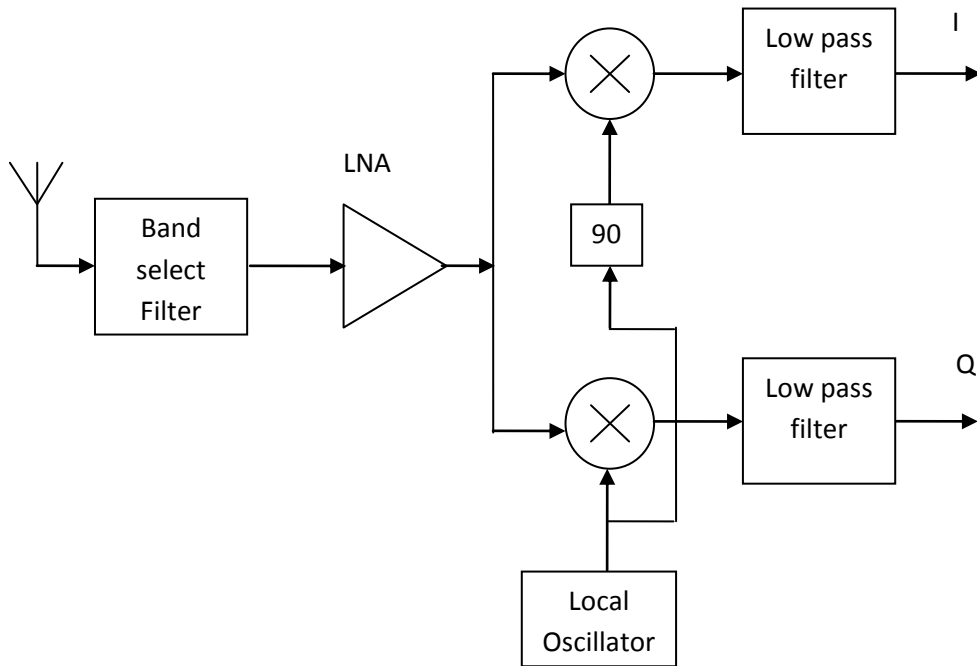


Figure 2. 2 Block Diagram of Direct Conversion Receiver

The advantages of this scheme are

- Low cost.
- No image problem.
- No image filters.

The disadvantages of this scheme are

- DC offset.
- I/Q mismatch.
- Even order nonlinearity.
- Flicker noise or – noise. This noise is very high in CMOS implementation.
- Local oscillator frequency planning while LO pulling and leakage.

In this receiver, DC offset and flicker noise are more dominant. Dc offset can be cancelled easily without impairing the signal information using capacitive coupling method or dc offset cancellation technique.

Usually, flicker noise arises from random trapping charge at the oxide silicon interface. For CMOS technology, corner frequency is high (around 1MHz). The remedy for this flicker

noise problem is by using passive mixers or by using vertical NPN transistors in CMOS technology for the switching core of active mixers.

On comparing the three transceiver architectures, we were selected the direct conversion scheme because of low power consumption, low cost and high integrable chip.

2.2 Transmitter Architectures

The choice of transmitter architecture is determined by two important factors: wanted and unwanted emission requirement and the number of oscillators and external filters. In general, the architecture and frequency planning of the transmitter must be selected in conjunction with those of the receiver so as to allow sharing hardware and possibility power [4].

2.2.1 Direct Conversion Architecture

In direct conversion transmitters, the output carrier frequency is equal to the LO frequency, and modulation and up conversion occur in the same circuit as shown in Figure. The simplicity of the topology makes it attractive for high level of integration.

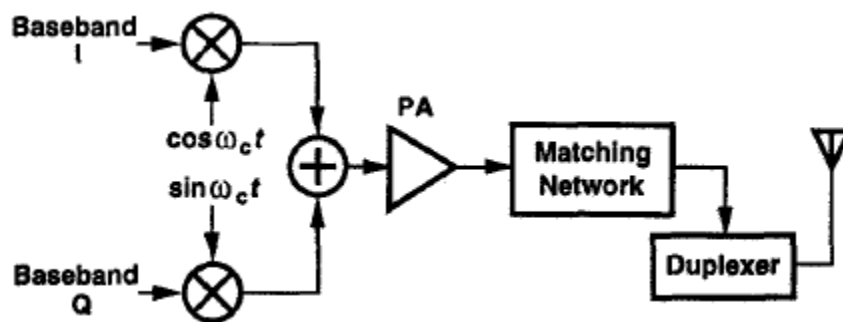


Figure 2. 3 Block Diagram of Direct Conversion Transmitter

The direct conversion architecture nonetheless suffers from an important drawback: disturbance of the local oscillator by the power amplifier output. Illustrated in Figure 2.4, this

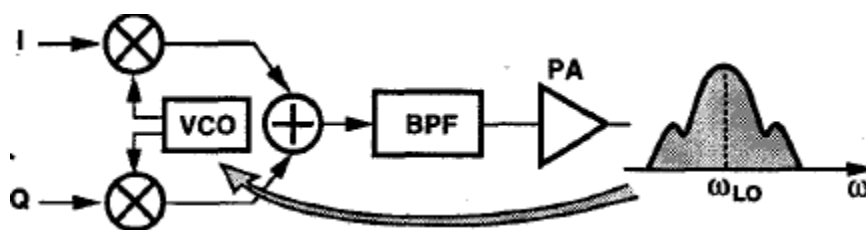


Figure 2. 4 LO pulling by PA

issue arises because the PA output is a modulated waveform having a high power and a spectrum centered around the LO frequency. Despite various shielding techniques employed to isolate the VCO, the noisy output of the PA still corrupts the oscillator spectrum. This corruption occurs through “injection pulling “ or “injection locking”, whereby the frequency of an oscillator tends to shift towards the frequency of the injected noise is close to the oscillator natural frequency, then the LO output is disturbed increasingly as the noise magnitude rises, eventually “locking” to noise frequency. In practice, noise levels as low as 40dB below the oscillation level may create tremendous disturbance.

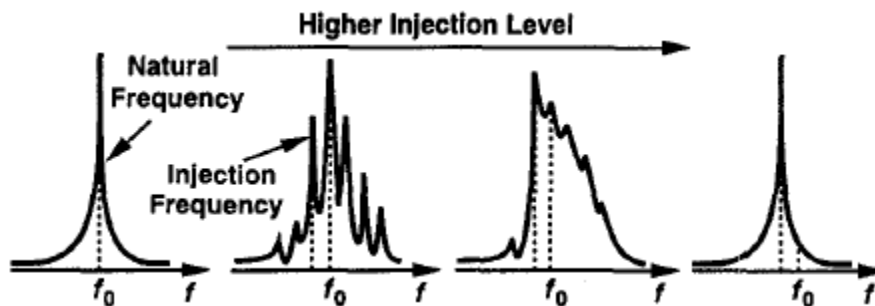


Figure 2.5 Injection pulling as the magnitude of the injected noise increases

The phenomenon of LO pulling is alleviated if the PA output spectrum is sufficiently far from the oscillator frequency. For Quadrature up conversion, this can be accomplished by “offsetting” the LO frequency, that is by adding or subtracting the output frequency of another oscillator. Figure 2.6 shows an example where the output signals of VCO₁ and VCO₂ are

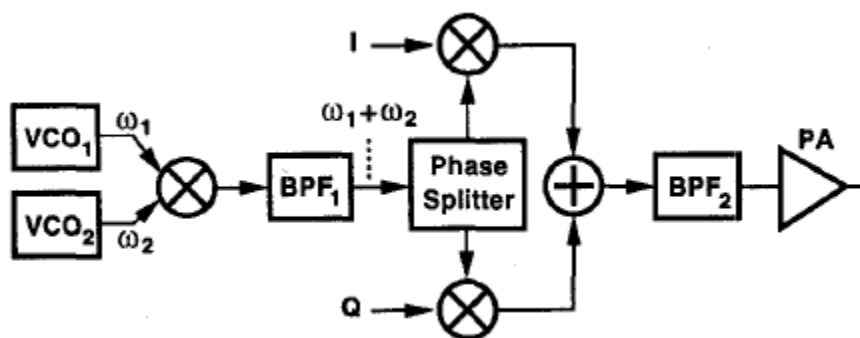


Figure 2.6 Direct conversion transmitter with offset LO

mixed and the result is filtered such that the carrier frequency is equal to $\omega_1 + \omega_2$, far from either ω_1 or ω_2 .

The selectivity of the first band pass filter, BPF₁, in Figure 2.6 impacts the quality of the transmitted signal. Owing to nonlinearities in the offset mixer, many spurs of the form $m\omega_1+n\omega_2$ appear at the input of BPF₁. If not adequately suppressed by the filter, such components degrade the quadrature generation of the carrier phases as well as create spurs in the up converted signal.

2.2.2 Two Step Architecture

Another approach to circumventing the problem of LO pulling in transmitters is to up convert the base band of signal in two (or more) steps so that the PA output spectrum is far from the frequency of the VCOs. As an example, consider the circuit shown in Figure 2.7. Here, the

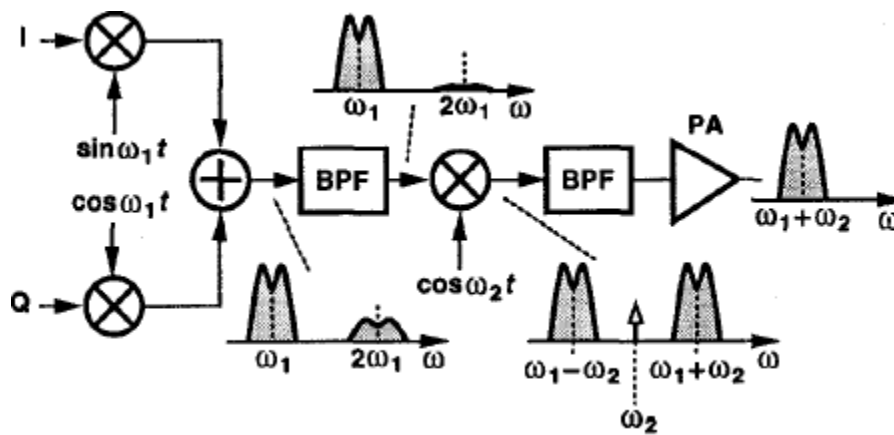


Figure 2.7 Two-step transmitter

baseband I and Q channels undergo quadrature modulation at a lower frequency, ω_1 [called the intermediate frequency (IF)], and the result is up converted to $\omega_1 + \omega_2$ by mixing and band pass filtering. The first BPF suppresses the harmonics of the IF signal while the second remove the unwanted sideband centered around $\omega_1 - \omega_2$.

An advantage of two-step up conversion over the direct approach is that since quadrature modulation is performed at lower frequencies, I and Q matching is superior, leading to less cross talk between the two bit streams. Also, a channel filter may be used at the first IF to limit the transmitted noise and spurs in adjacent channels.

The difficulty in two-step transmitters is that the band pass filter following the second up conversion must reject the unwanted sideband by a large factor, typically 50 to 60dB. This is because the simple up conversion missing sidebands with equal magnitudes. Owing to the higher centre frequency, this filter is typically a passive, relatively expensive off-chip device.

2.3 Design of Zigbee Transmitter

CMOS RF Front-end for IEEE 802.15.4

The Architecture of the Zigbee Frontend is shown in Figure 2.8, block diagram is shown in Figure 2.9.

RF Front-end for IEEE 802.15.4

Architecture:

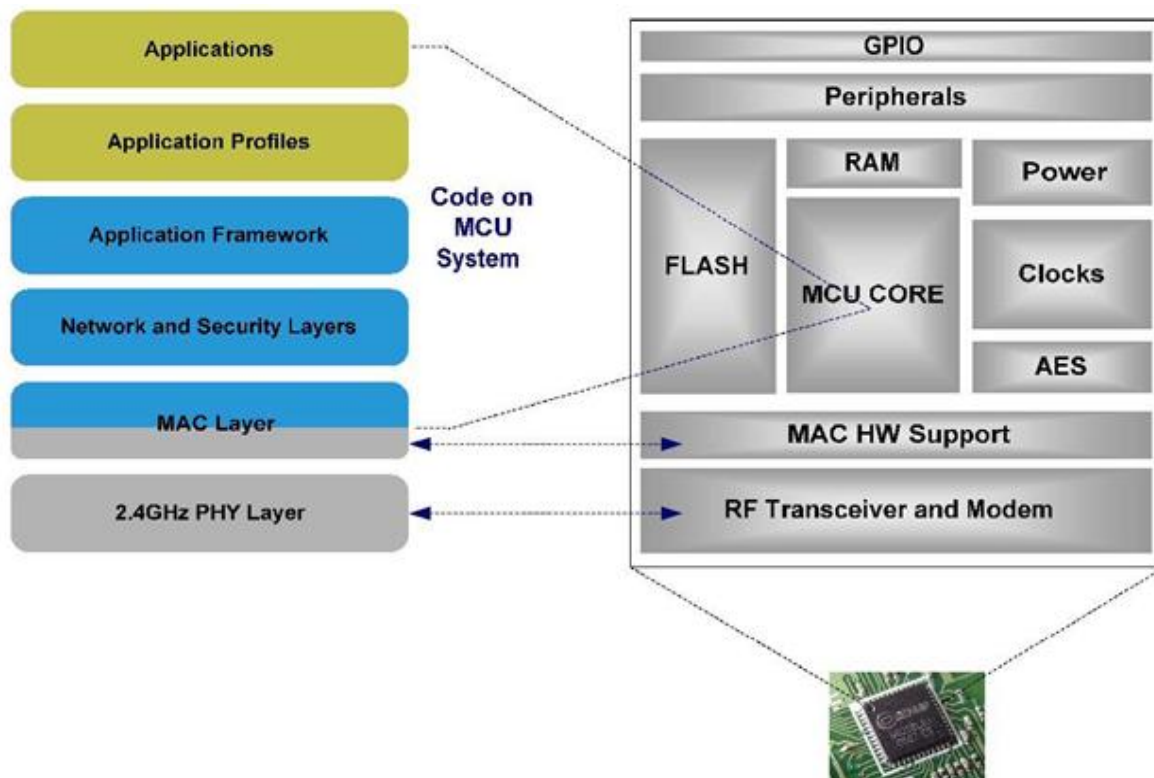


Figure 2.8 RF Front end for IEEE 802.15.4

IEEE 802.15.4 assigns three frequency bands of operation: the 868-MHz, 915-MHz, and 2.4-GHz unlicensed industrial, scientific, and medical (ISM) bands. Among the three, the 2.4-GHz band is highly attractive, since this unlicensed band is commonly available throughout the world. Typical applications of this low data rate standard include those for industrial and commercial uses, home automation, PC peripherals, consumer electronics, and personal health care appliances, as well as for toys and games that should be able to run for six months to two years on just button cells or batteries[3].

2.3.1 Specifications for the IEEE 802.15.4 RF Frontend

Table 2. 1 Specification of Zigbee technology

S.No	Parameter	Specification
1.	Operating frequency	2.45GHz
2.	Supply Voltage	1.8V
3.	Spread spectrum	Direct Sequence Spread Spectrum
4.	Modulation	OQPSK
5.	Number of channels	16
6.	Data rate	250 kbps
7.	Channel spacing	5 MHz

In this Thesis Zigbee Transmitter is designed in 0.18um CMOS technology operated at 1.8v supply voltage. Here Zigbee Transmitter employs Direct Sequence Spread spectrum and used OQPSK as a modulation scheme. An IEEE 802.15.4-based 2.4-GHz PHY can support 250 kb/s data rate. Sixteen channels are available for 2.4-GHz band applications, with channel spacing of 5 MHz.

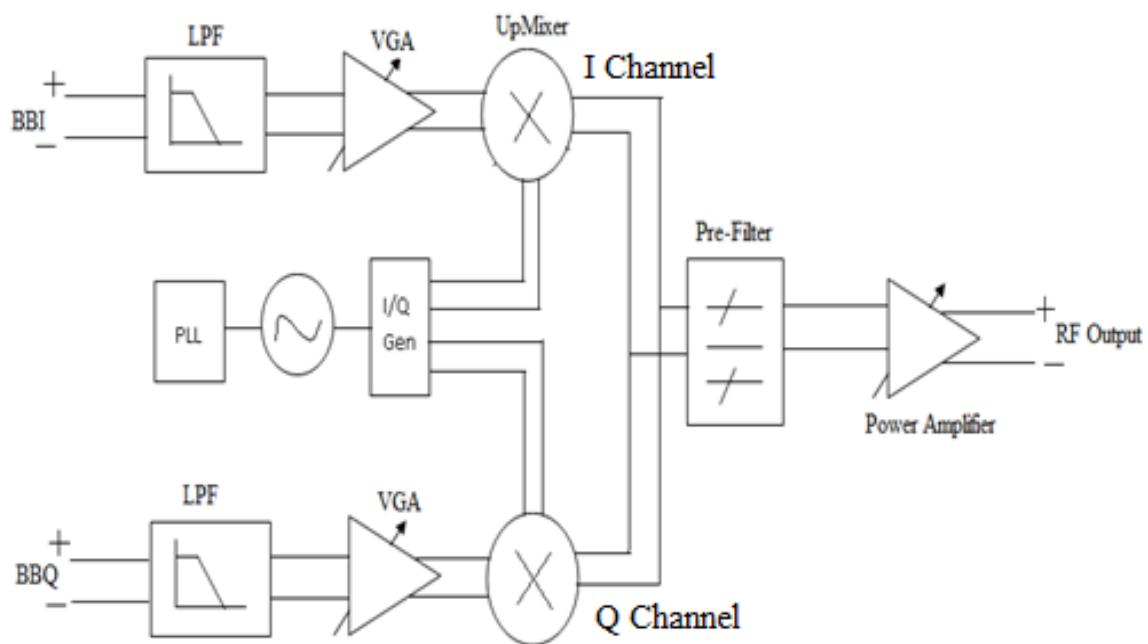


Figure 2. 9 Zigbee transmitter architecture

As shown in Figure 2.9 Zigbee Transmitter comprises of Low Pass Filter, Variable Gain Amplifier, up conversion Mixer, Power Amplifier. The Low Pass Filter allows low frequency range signal and attenuates all other high frequency signals.

The Variable Gain Amplifier stabilizes the amplitude of the LPF output signal and provides a constant amplitude signal to the following blocks. The circuit design details are discussed in following Chapter 3.

The Mixer translates signals from one frequency band to another. The output of the mixer consists of multiple images of the mixers input signal where each image is shifted up or down by multiples of the local oscillator (LO) frequency. The circuit design details are discussed in following Chapter 4.

The Power Amplifier converts a low-power radio-frequency signal into a larger signal of significant power, typically for driving the antenna of a transmitter. In this thesis Class A Power Amplifier which comes under Linear amplifier is designed. The circuit design details are discussed in following Chapter 5.

Chapter-3

Design of a Variable Gain Amplifier

3.1 Introduction

VARIABLE gain amplifiers (VGAs) can be found in many applications and are used to maximize the dynamic range of overall systems in medical equipments, telecommunication systems, hearing aids, disk drives, and others[5]-[9]. In disk drives and CCD imaging equipments, the VGAs play the important role of stabilizing the amplitude of the output signal under various conditions and supply a constant-amplitude signal to the detector and filter sections of the read channel. The VGA for these applications requires a gain variation range of more than 30dB. In communication systems, the VGA is normally employed in a feedback loop to implement an automatic gain control (AGC) amplifier.

The AGC amplifier is a circuit that automatically controls its gain in response to the amplitude of the input signal, leading to a constant-amplitude output. The gain as an exponential function of control voltage, which is not an easily obtainable characteristic in CMOS technology, is desirable for minimizing the settling time of the AGC loops. Moreover, code-division multiple-access (CDMA) systems require VGAs with high linearity and wide range of gain variation.

As an all-CMOS implementation, there are two approaches used to realize VGAs depending on whether the control signal is digital or analog. The digitally controlled VGAs use a series of switchable resistors or switched-capacitor techniques to control gain as shown in Figure. 3.1(a). In digitally controlled VGAs, gain varies as a discrete function of the control signal, which can lead to discontinuous signal phases that can cause problems in many systems.

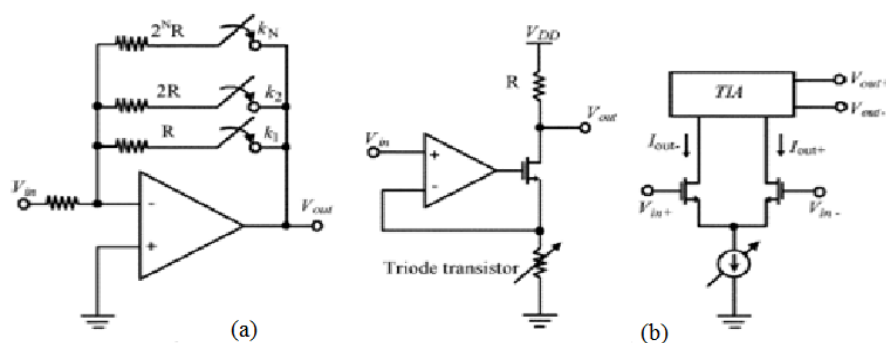


Figure 3. 1 (a) Digital Controlled VGA, (b) Analog Controlled VGA

In order to reduce the amount of jumps, a large number of control bits are required with digitally controlled VGAs. Therefore, for applications that require smooth gain transitions, the VGAs controlled by analog signal are preferred. The VGAs controlled by analog signals typically adopt variable transconductance or resistance stages for gain variation as shown in Figure. 3.1(b). With these topologies, the gains can be controlled continuously, but obtaining a wide exponential gain variation as a function of control voltage is a big issue, especially in CMOS technology.

In cellular wireless communication systems, the amplitude of the receiver and transmitter signals varies greatly. For this reason, for example, in a CDMA system, the transceiver requires at least 80 dB of dynamic gain variation and splits into RF and IF/baseband stages. In a typical receiver, most of the gain variation is assigned to the baseband stage. Therefore, to cover such a wide dynamic range, conventional CMOS-based VGAs require at least 4 or 5 gain-varying stages. The multiple gain-varying stages lead to a higher amount of power dissipation, larger chip area, and higher cost.

3.2 Decibel Linear Function

The pseudo-exponential and Taylor series approximation functions used for VGA designs are given, respectively [7],

$$\text{---} \tag{1}$$

$$\text{---} \text{ ---} \tag{2}$$

= -

by where is a constant and an independent variable. The plots of (1), (2), and the ideal exponential function in decibel scale as a function of are shown in Figure. 3.2, Equations (1) and (2) approximate the exponential function when. Otherwise, (1) and (2) deviate significantly from the ideal exponential function. As can be seen in Figure. 3.2, (1) and (2) provide less than 15- and 12-dB linear range with a linearity error of less than 0.5 dB.

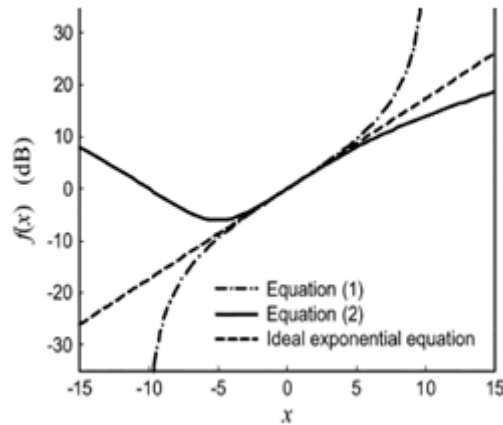


Figure 3. 2 Decibel scale plots of (1), (2) and the ideal exponential function

Compared to (1) and (2), the new approximated exponential function, is

$$\frac{x^2 + k}{x^2 - k} \quad (3)$$

Where is a k constant. The numerator and denominator of (3) are squaring functions of the variable x . For k less than unity, the decibel linear range of (3) extends drastically and reaches its maximum value at around $k = 0.12$. As can be seen in Figure. 3.3, the decibel linear range of (3) extends to more than 60 dB with a linearity error of less than 0.5 dB for (solid line), which is a significant improvement compared to (1) and (2).

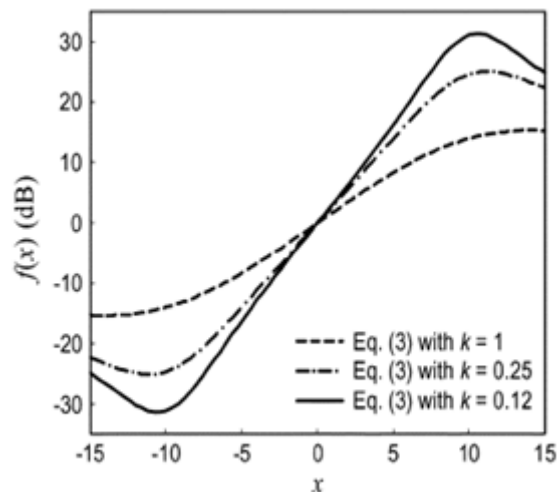


Figure 3. 3 : Decibel scale plots of (3) for various values of k

3.3 Variable Gain Amplifier Design

The Basic buliding blocks of Variable Gain Amplifier are (a).Control circuit,(b).Amplifier Block,(c).Buffer Block.

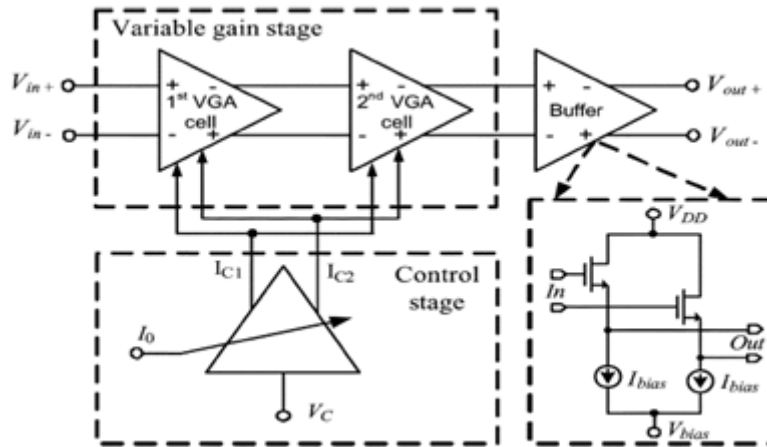


Figure 3. 4 Block Diagram of Two Stage Variable Gain Amplifier

3.3.1 Control Circuit Block

The control circuit block generates the numerator and denominator of (3), where all the transistors are assumed to be in saturation mode. In Figure. 3.5, the body terminals of pMOS and nMOS transistors are tied to supply voltages V_{DD} and V_{SS} respectively, and the lengths of transistors M_{18} , M_{24} and are chosen long enough that the channel length modulation can be neglected.

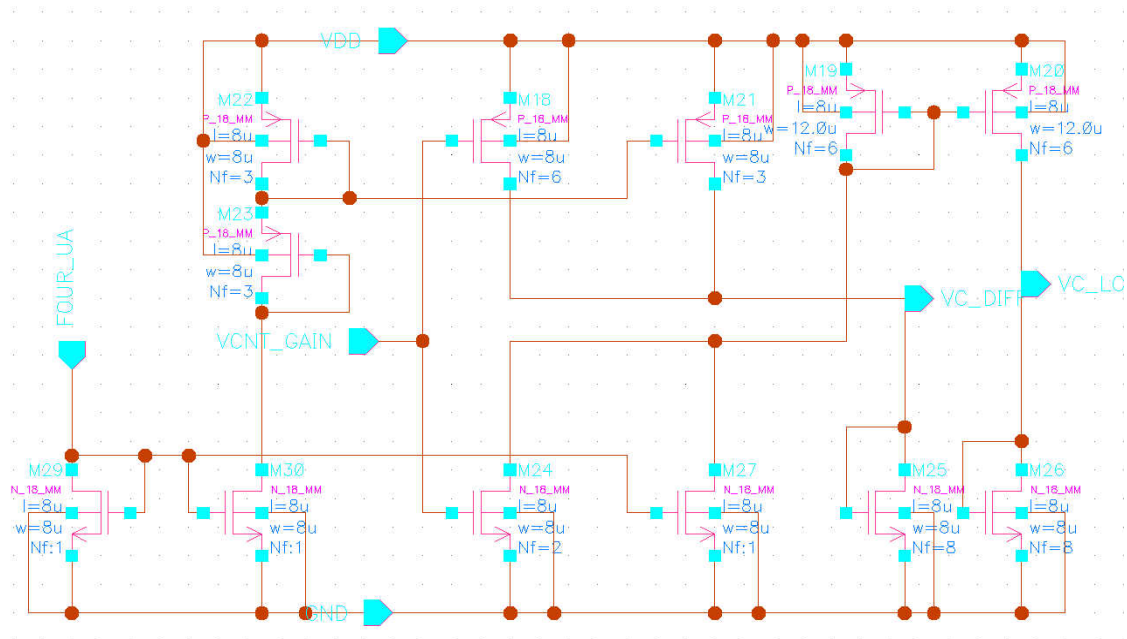


Figure 3. 5 Schematic of Control Stage

In Figure. 3.5, to guarantee the saturation-mode operation of transistors M_{18} and M_{24} the control voltage must stay within a range of $(V_{SS}+V_{THn})\sim(V_{DD}-|V_{THp}|)$, where V_{THn} ,

V_{THp} are the threshold voltages of nMOS and pMOS transistors, respectively. The drain currents of transistors M_{18} , M_{24} in Fig. 3.5 can be given as

$$I_{D1} = \frac{K_p}{2} (V_{DD} - V_{THp})^2 \quad (4)$$

$$I_{D2} = \frac{K_n}{2} (V_{DD} - V_{THn})^2 \quad (5)$$

where K_p , K_n are constants [$K_p = (W_1/2L_1)\mu_p C_{ox}$ and $K_n = (W_2/2L_2)\mu_n C_{ox}$]. In Figure. 3.5, since the current I_{C1} and I_{C2} are $I_{D1}+I_0$ and $I_{D2}+I_0$ respectively, the resulting currents I_{C1} and I_{C2} assuming $K_p = K_n = K$, $V_{DD} = -V_{SS}$ and $|V_{THp}| = V_{THn} = V_{TH}$, the ratios of I_{C1} and I_{C2} is given by

$$\frac{I_{C1}}{I_{C2}} = \frac{I_{D1} + I_0}{I_{D2} + I_0} \quad (6)$$

The VGA that adopts (6) shows a wide range of gain variation however, the required dynamic gain range for different applications is not equal; therefore, if the VGA provides a wider range of gain variation than the requirement, then the range of the control signal is reduced. Consequently, in order to maximize the range of control signal, the gain variation range of the VGA should be controllable.

3.3.2 Amplifier Block

The circuit schematic of the amplifying block that is adopted for the VGA, including the common-mode feedback circuit. In Figure 3.6, the amplifier consists of an input Source-coupled pair (M4 and M5) and diode-connected loads (M6 and M7). The sizes of M4 and M6 are equal to M5 and M7 respectively. In Figure 3.6, the two currents and from the control block in Figure 3.5 are mirrored to M28 and M31. Therefore, the differential gain of the VGA shown in Figure 3.6 can be expressed as

$$A_V = \frac{g_{m-input}}{g_{m-load}} \quad (7)$$

Where $g_{m-input}$ is the transconductance of the input transistors (M4 and M5) and g_{m-load} the transconductance of the diode connected transistors (M6 and M7), respectively.

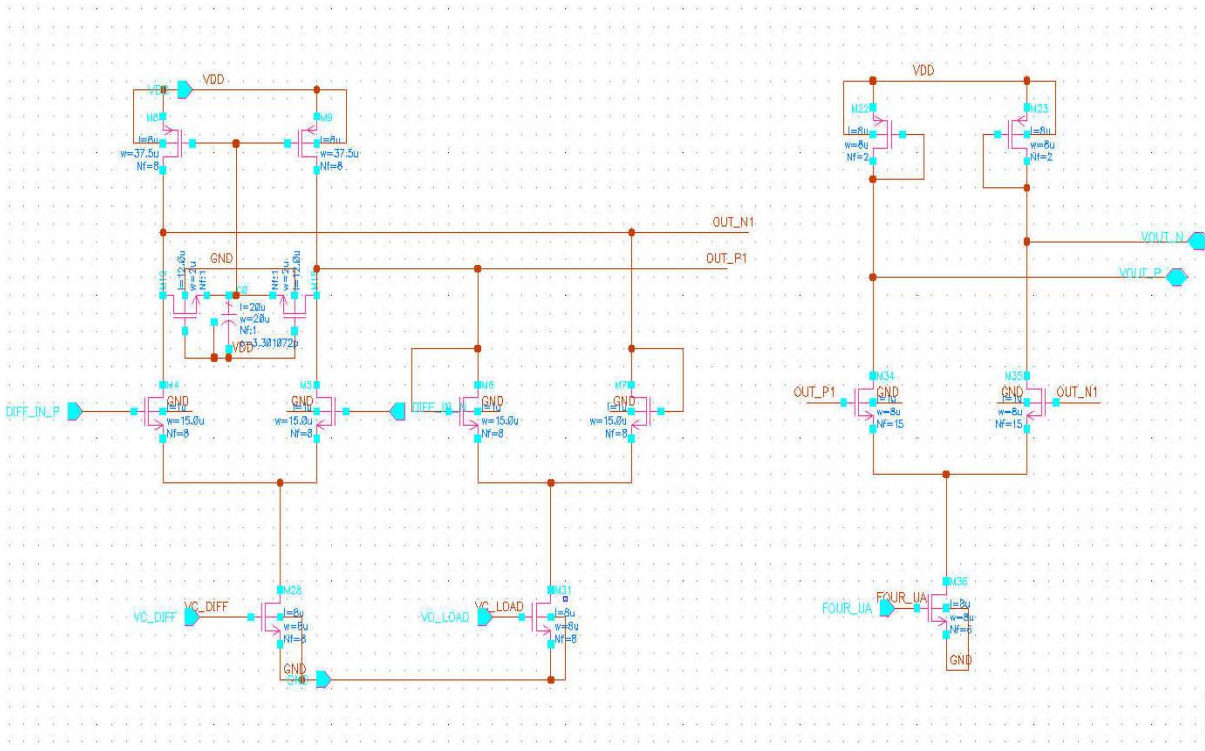


Figure 3. 6 Schematic of Amplifier Stage

From (6) and (7), the differential gain as a function of the control voltage is given by

$$A_V = \frac{g_{m1} g_{m2} g_{m3} g_{m4} g_{m5} g_{m6} g_{m7} g_{m8} g_{m9} g_{m10} g_{m11} g_{m12} g_{m13} g_{m14} g_{m15} g_{m16} g_{m17} g_{m18} g_{m19} g_{m20} g_{m21} g_{m22} g_{m23} g_{m24} g_{m25} g_{m26} g_{m27} g_{m28} g_{m29} g_{m30} g_{m31} g_{m32} g_{m33} g_{m34} g_{m35} g_{m36} g_{m37} g_{m38} g_{m39} g_{m40} g_{m41} g_{m42} g_{m43} g_{m44} g_{m45} g_{m46} g_{m47} g_{m48} g_{m49} g_{m50} g_{m51} g_{m52} g_{m53} g_{m54} g_{m55} g_{m56} g_{m57} g_{m58} g_{m59} g_{m60} g_{m61} g_{m62} g_{m63} g_{m64} g_{m65} g_{m66} g_{m67} g_{m68} g_{m69} g_{m70} g_{m71} g_{m72} g_{m73} g_{m74} g_{m75} g_{m76} g_{m77} g_{m78} g_{m79} g_{m80} g_{m81} g_{m82} g_{m83} g_{m84} g_{m85} g_{m86} g_{m87} g_{m88} g_{m89} g_{m90} g_{m91} g_{m92} g_{m93} g_{m94} g_{m95} g_{m96} g_{m97} g_{m98} g_{m99} g_{m100}}{g_{m1} g_{m2} g_{m3} g_{m4} g_{m5} g_{m6} g_{m7} g_{m8} g_{m9} g_{m10} g_{m11} g_{m12} g_{m13} g_{m14} g_{m15} g_{m16} g_{m17} g_{m18} g_{m19} g_{m20} g_{m21} g_{m22} g_{m23} g_{m24} g_{m25} g_{m26} g_{m27} g_{m28} g_{m29} g_{m30} g_{m31} g_{m32} g_{m33} g_{m34} g_{m35} g_{m36} g_{m37} g_{m38} g_{m39} g_{m40} g_{m41} g_{m42} g_{m43} g_{m44} g_{m45} g_{m46} g_{m47} g_{m48} g_{m49} g_{m50} g_{m51} g_{m52} g_{m53} g_{m54} g_{m55} g_{m56} g_{m57} g_{m58} g_{m59} g_{m60} g_{m61} g_{m62} g_{m63} g_{m64} g_{m65} g_{m66} g_{m67} g_{m68} g_{m69} g_{m70} g_{m71} g_{m72} g_{m73} g_{m74} g_{m75} g_{m76} g_{m77} g_{m78} g_{m79} g_{m80} g_{m81} g_{m82} g_{m83} g_{m84} g_{m85} g_{m86} g_{m87} g_{m88} g_{m89} g_{m90} g_{m91} g_{m92} g_{m93} g_{m94} g_{m95} g_{m96} g_{m97} g_{m98} g_{m99} g_{m100}} \quad (8)$$

From Figure. 3.6, the amplifier gain can be varied by controlling the current through transistors and M28 and M31. Since the amplifier adopts current sources as active loads, the currents through transistors M8 and M9 must also vary accordingly. From (6), the sum of the currents through and is given as

$$I_{C1} + I_{C2} = 2K \left(1 + \frac{g_{m1} g_{m2} g_{m3} g_{m4} g_{m5} g_{m6} g_{m7} g_{m8} g_{m9} g_{m10} g_{m11} g_{m12} g_{m13} g_{m14} g_{m15} g_{m16} g_{m17} g_{m18} g_{m19} g_{m20} g_{m21} g_{m22} g_{m23} g_{m24} g_{m25} g_{m26} g_{m27} g_{m28} g_{m29} g_{m30} g_{m31} g_{m32} g_{m33} g_{m34} g_{m35} g_{m36} g_{m37} g_{m38} g_{m39} g_{m40} g_{m41} g_{m42} g_{m43} g_{m44} g_{m45} g_{m46} g_{m47} g_{m48} g_{m49} g_{m50} g_{m51} g_{m52} g_{m53} g_{m54} g_{m55} g_{m56} g_{m57} g_{m58} g_{m59} g_{m60} g_{m61} g_{m62} g_{m63} g_{m64} g_{m65} g_{m66} g_{m67} g_{m68} g_{m69} g_{m70} g_{m71} g_{m72} g_{m73} g_{m74} g_{m75} g_{m76} g_{m77} g_{m78} g_{m79} g_{m80} g_{m81} g_{m82} g_{m83} g_{m84} g_{m85} g_{m86} g_{m87} g_{m88} g_{m89} g_{m90} g_{m91} g_{m92} g_{m93} g_{m94} g_{m95} g_{m96} g_{m97} g_{m98} g_{m99} g_{m100}}{g_{m1} g_{m2} g_{m3} g_{m4} g_{m5} g_{m6} g_{m7} g_{m8} g_{m9} g_{m10} g_{m11} g_{m12} g_{m13} g_{m14} g_{m15} g_{m16} g_{m17} g_{m18} g_{m19} g_{m20} g_{m21} g_{m22} g_{m23} g_{m24} g_{m25} g_{m26} g_{m27} g_{m28} g_{m29} g_{m30} g_{m31} g_{m32} g_{m33} g_{m34} g_{m35} g_{m36} g_{m37} g_{m38} g_{m39} g_{m40} g_{m41} g_{m42} g_{m43} g_{m44} g_{m45} g_{m46} g_{m47} g_{m48} g_{m49} g_{m50} g_{m51} g_{m52} g_{m53} g_{m54} g_{m55} g_{m56} g_{m57} g_{m58} g_{m59} g_{m60} g_{m61} g_{m62} g_{m63} g_{m64} g_{m65} g_{m66} g_{m67} g_{m68} g_{m69} g_{m70} g_{m71} g_{m72} g_{m73} g_{m74} g_{m75} g_{m76} g_{m77} g_{m78} g_{m79} g_{m80} g_{m81} g_{m82} g_{m83} g_{m84} g_{m85} g_{m86} g_{m87} g_{m88} g_{m89} g_{m90} g_{m91} g_{m92} g_{m93} g_{m94} g_{m95} g_{m96} g_{m97} g_{m98} g_{m99} g_{m100}} \right) \quad (9)$$

which is a second-order polynomial of the control voltage V_C . As a result, the drain currents through transistors M28 and M31 vary as a function of gain variation. Therefore, the strong common-mode feedback circuit shown in Figure. 3.6 is required in order to prevent any of the transistors from entering linear mode operation and to maintain a specific dc value for the biasing of the next stage.

3.3.3 Buffer Block

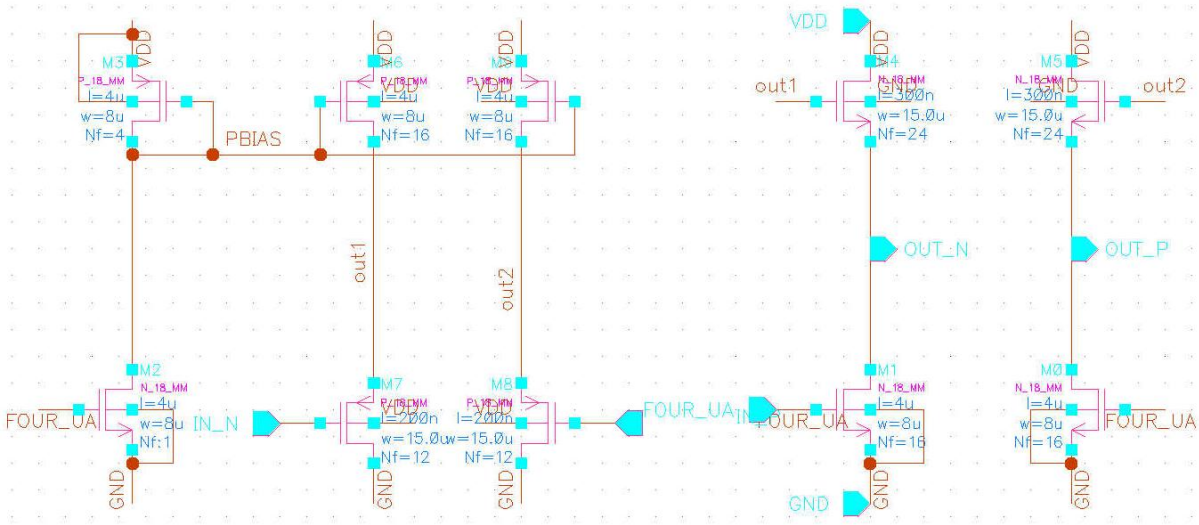


Figure 3. 7 Schematic of Buffer Stage

The buffer is designed as a differential source follower, in which the gates of the input different transistors are differential inputs of the buffer with high impedance while the output impedance can be adjusted to 50Ω by a proper choice of the bias current and the size of input different transistors of the buffer. The buffer in Figure 3.7 is added for the convenience of measurements, providing high-input and 50Ω output impedances.

3.4 The Single Stage Overall VGA

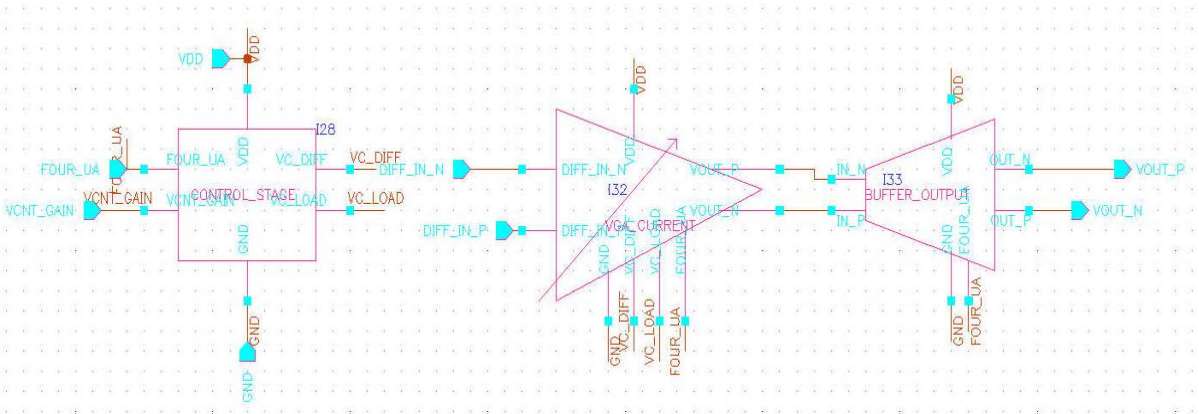


Figure 3. 8 Schematic of Single Stage Overall VGA

Regarding the frequency response, assuming that the VGA is evaluated under a 50Ω environment, the bandwidth of the VGA is dominated by the pole at the input and the inter-stage node between two amplifiers. The input pole is a function of the input capacitance and resistance. Due to the Miller effect, the input capacitance is proportional to the amplifier gain; therefore, the bandwidth is reduced at higher gain settings. The output pole is proportional to the output capacitance and resistance. Since the resistance from the inter-stage node to the ac

ground is dominated by the diode-connected transistors M6 and M7 in Figure 3.6, which vary as a function of gain, the bandwidth of the amplifier varies accordingly. At higher gains, the current flowing through the diode-connected transistors is reduced leading to narrower bandwidths. Since the currents flow through M6 and M7 are squaring functions of the control voltage, the bandwidth of the VGA varies significantly from low- to high-gain modes.

3.5 Results and Discussion

Table 3. 1 Vcontrol versus VGA output (Gain dB)

S. No	V _{control} (mV)	VGA OP (dB)
1	200	39.9
2	241.9	39.55
3	283.87	38.58
4	325.8	37.96
5	367.7	36.29
6	409.67	33.99
7	451.6	31.31
8	493.55	28.5
9	535.5	25.77
10	577.4	23.13
11	619.5	20.59
12	661.29	18.15
13	703.22	15.8
14	745.16	11.24
15	787	9
16	829	6.74
17	870.96	6.79
18	912.9	4.54
19	954.8	2.27
20	996.77	-71.8
21	1.0387	-2.46
22	1.0806	-4.9

23	1.1225	-7.43
24	1.1645	-10.069
25	1.2	-12.5
26	1.248	-15.5
27	1.29	-17.99
28	1.33	-19.845
29	1.374	-20.985
30	1.416	-21.595
31	1.5	-22

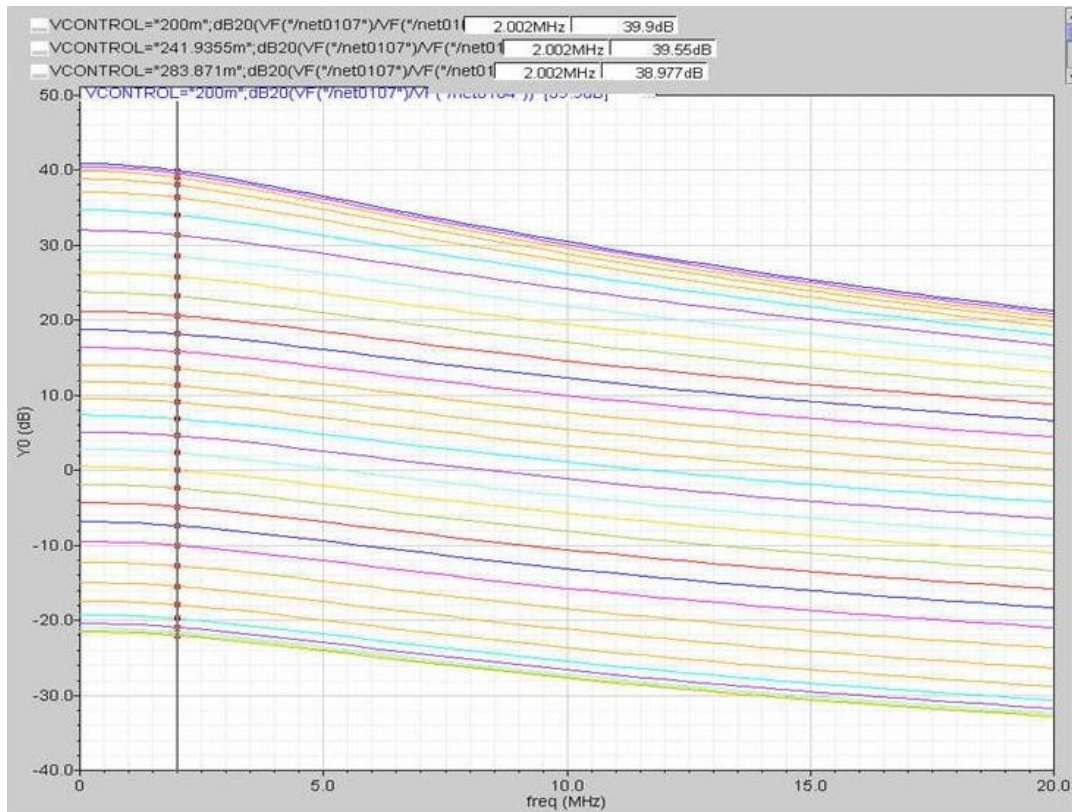


Figure 3. 9 Frequency versus Gain for Various Control voltages

The Proposed single stage Variable Gain Amplifier shows a maximum gain variation of 62dB (from 40 to -22), while dissipating an average current of 630u A from a 1.8v supply.

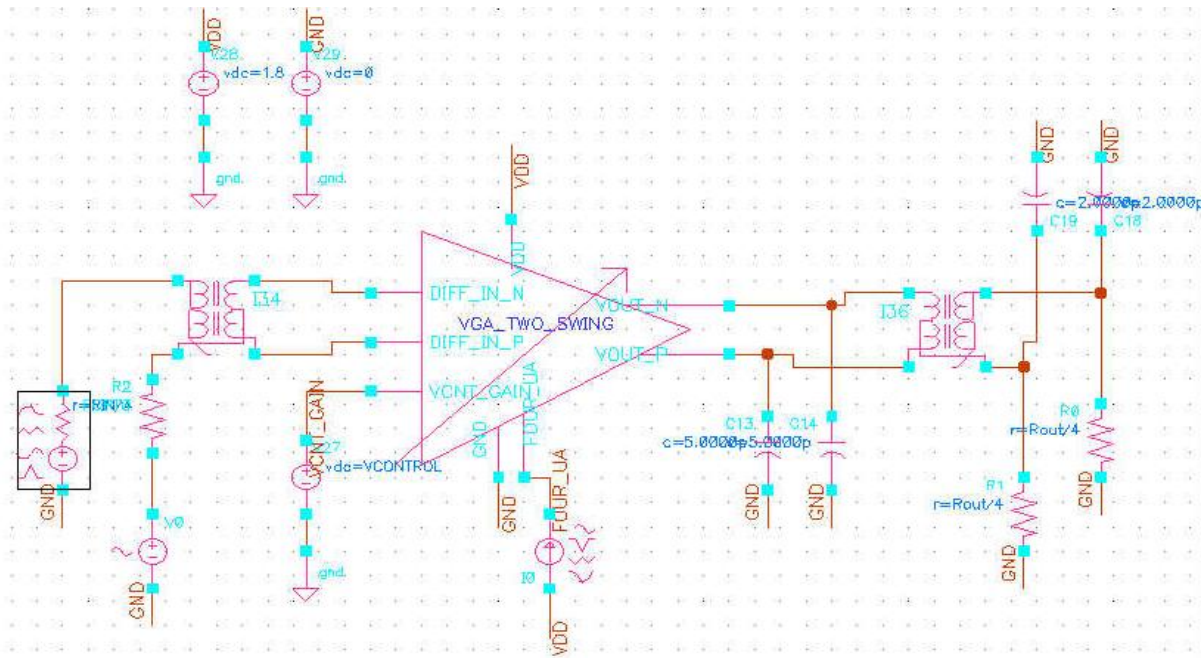


Figure 3. 10 Schematic of Proposed VGA Setup

The VGA setup as shown in the Figure 3.10 is simulated in Cadence© using SpectreRF simulator in UMC-0.18um Mixed Signal CMOS RF models. The VGA is designed to operate at 1.8v supply voltage. Chosen transient, dc, ac analysis for simulation and observed the gain variation of 62dB (from 40dB to -22dB).

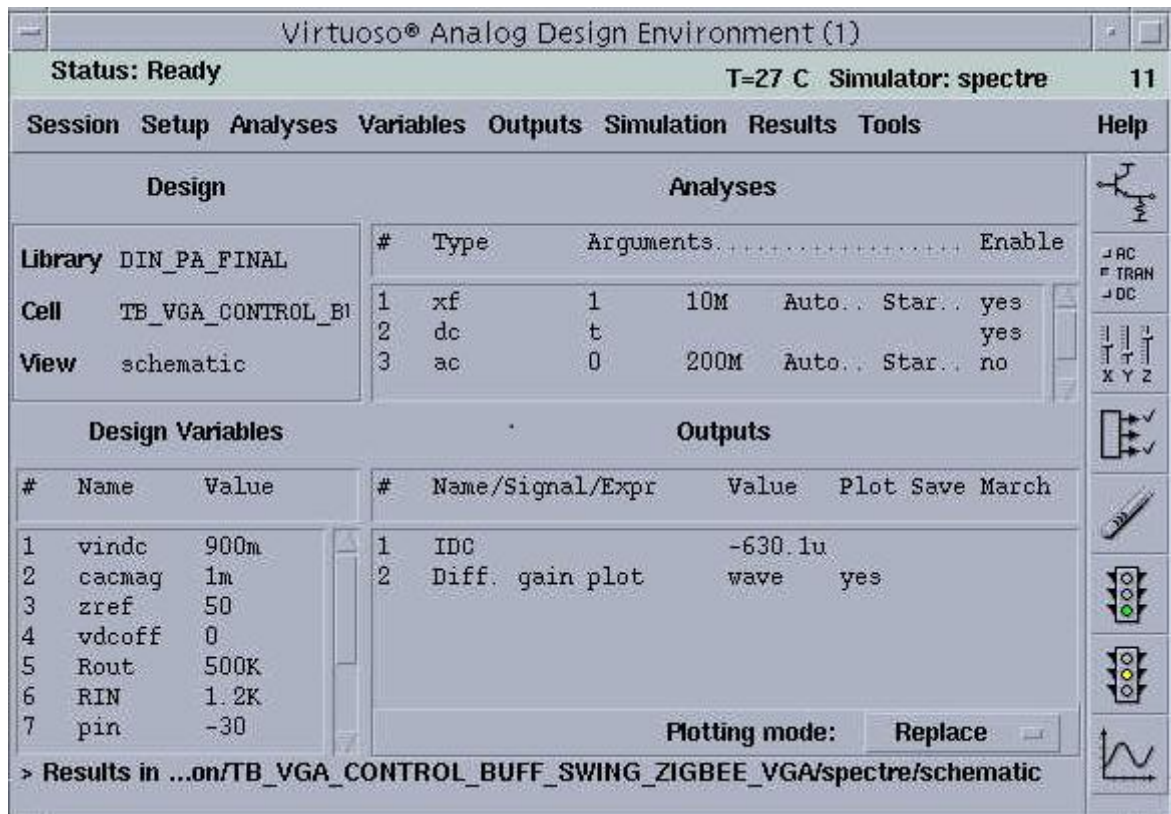


Figure 3. 11 Analog Design Environment for VGA Setup

3.5.1 Layout Issues

In Differential topology, to achieve better matching, transistors are arranged in a symmetric, common-centroid structure along with dummy transistors so that current flows symmetrically from left to right. The failure mechanisms for electrical overstress, such as electro-migration and antenna effect are also considered for the layout. To sustain the large currents in different parts of the PA circuit, wide tracks and stacked metal layers are used. The transistors which have larger width. This demands the use of multifinger and folded transistors connected in parallel to reduce the resistance and obtain better current distribution. Different blocks are encapsulated with guard-rings to avoid cross-talk and decouple substrate noise. The layout of the Variable Gain Amplifier is displayed in Figure. 3.12. The total chip area is (250 μm x 167.3 μm).

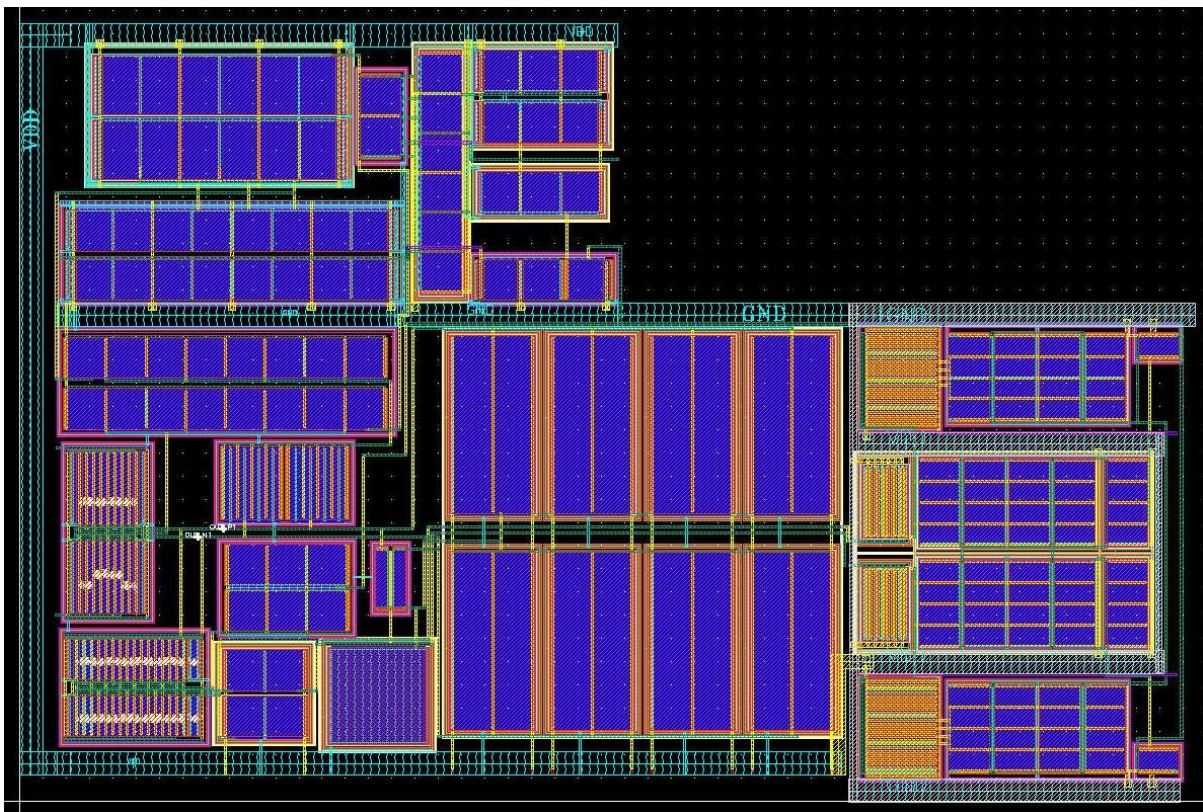


Figure 3. 12 Layout of Single stage variable gain amplifier

After creating Layout for VGA, we go for DRC to check all the process specific design rules have been met. Then we compare our layout with the schematic that we made earlier to see if they are both the same .Once the netlists matched we go for Post layout simulation. For performing Post layout simulation, an **analog_extracted** view for the VGA is required. So we generate a config window as shown in the Figure 3.13 and do the post layout simulation same as like schematic simulation.

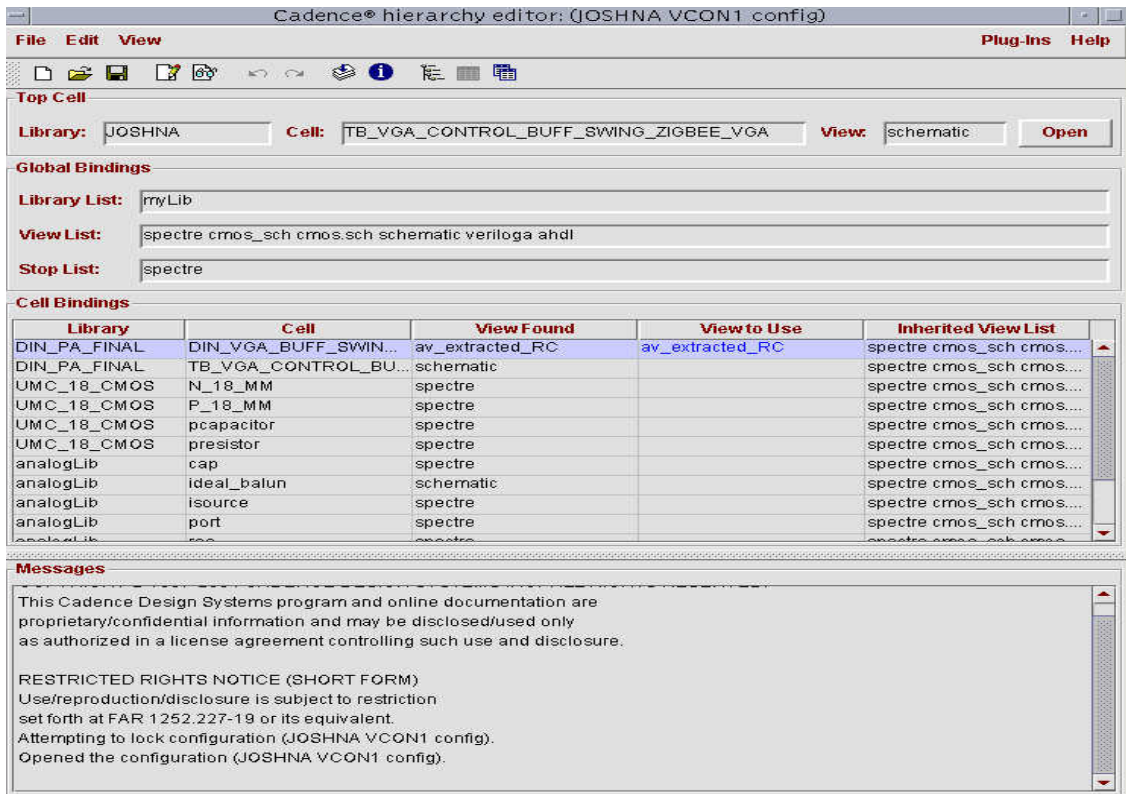


Figure 3. 13 Config Window of VGA for Analog Extracted View

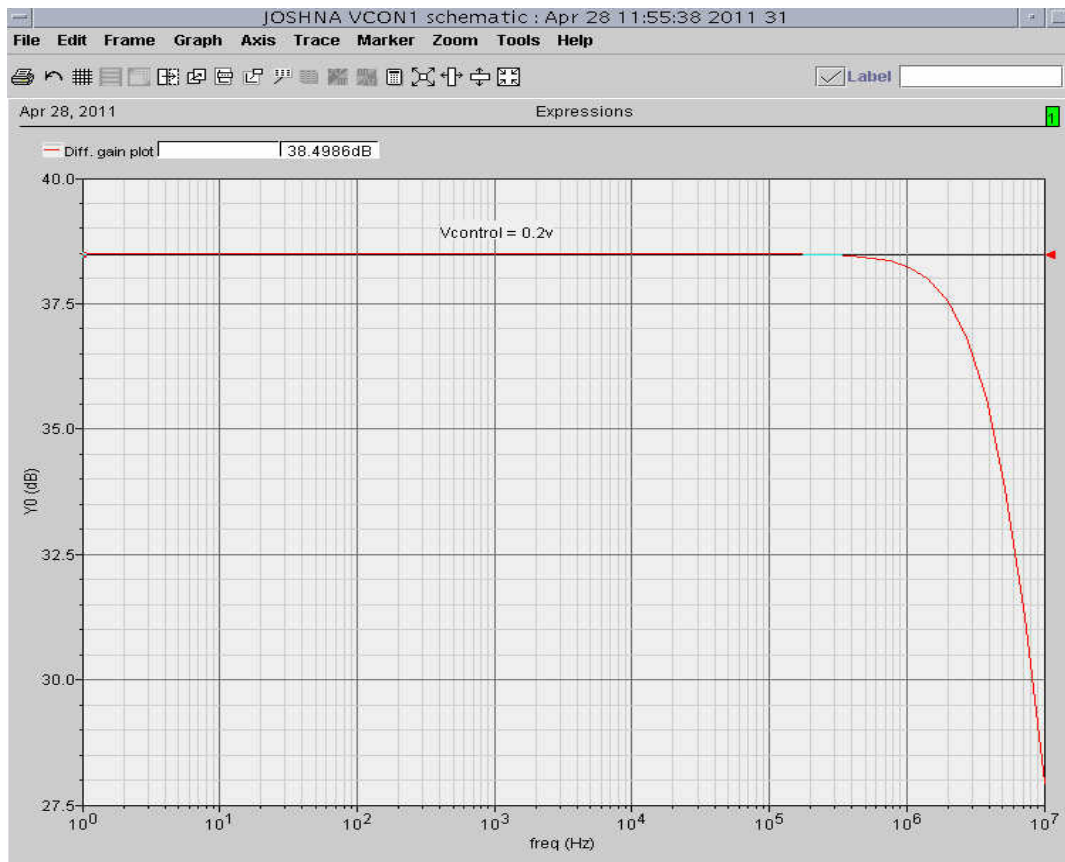


Figure 3. 14 Post-Layout Simulations for VGA

The Post layout simulation for VGA as shown in the Figure 3.14 differs slightly from schematic simulation due to the influence of circuit parasitics such as parasitic capacitances and resistances.

Chapter-4

Design of a Up-Conversion Mixer

4.1 Introduction

In RF communication systems, mixers play a key role. In these systems, many functions are implemented with mixers, such as down conversion, up conversion, product detection, I/Q modulation, phase locked loops, etc. Mixers are key components in both receivers and transmitters. Mixers translate signals from one frequency band to another. The output of the mixer consists of multiple images of the mixers input signal where each image is shifted up or down by multiples of the local oscillator (LO) frequency. The most important mixer output signals are usually the signals translated up and down by one LO frequency.

In an ideal situation, the mixer output would be an exact replica of the input signal. In reality mixer output is distorted due to non-linearity in the mixer. In addition, the mixer components and a non-ideal LO signal introduce more noise to the output. Bad design might also cause leakage effects, complicating the design of the complete system. Linearity is important to transmitter performance, where you want an error-free output signal.

The Up Conversion mixers are one of the key building blocks in all those transmission systems[10]. A carefully designed and integrated mixer contain several good qualities: large conversion gain, good LO to RF isolation, small noise figure, and excellent linearity.

The mixer, as a nonlinear circuit by definition, is the most critical analog building block in the Zigbee Transceiver. One typical transmitter architecture applied in Zigbee system shown in Figure 4.1.

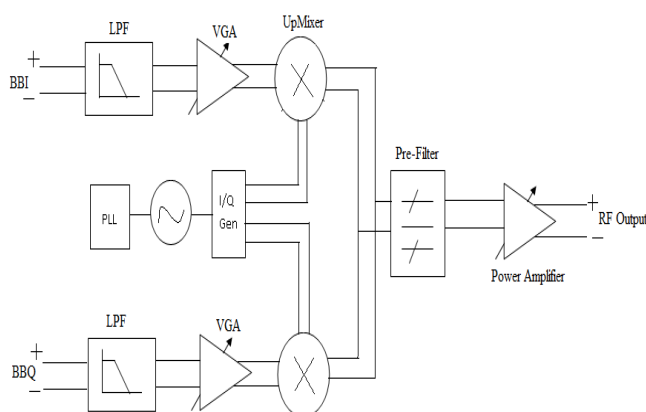


Figure 4. 1 Zigbee Transmitter Architecture

4.2 Mixer Topology

4.2.1 Gilbert Cell

The linearity of an RF mixer is in most cases rather limited. The Gilbert topology is the most common used in a CMOS technology[11]. Its operation is based on a translinear configuration. Techniques like predistortion and emitter degeneration are necessary to obtain a reasonable linearity. In CMOS a double balanced structure which cancels out the quadratic term of the MOS transistor can be used. These mixers have not only a limited linearity which highly depends on matching, even more important I_{ss} their limited frequency range. The input transistors of these mixers can only be biased with a relatively small $V_{GS} - V_{TH}$, in order to keep them in saturation at all times.

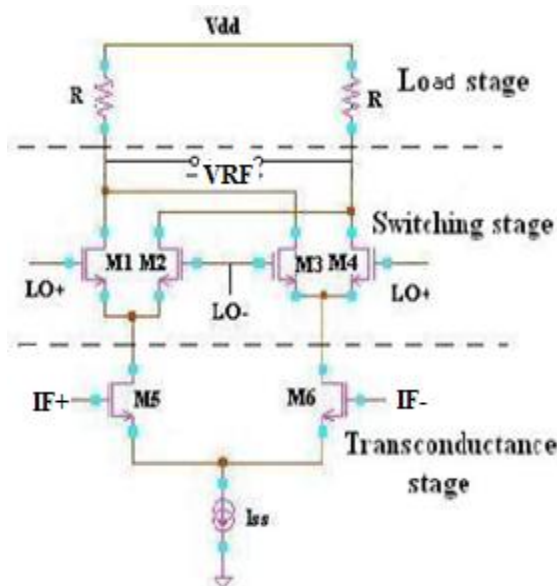


Figure 4. 2 Schematic of Conventional Gilbert Mixer

A schematic representation of the Gilbert mixer is shown in Figure.4.2. A Gilbert-cell mixer is able to achieve high RF-LO isolation, high dynamic range, and also cancel even-order inter-modulation products two single-balanced circuits with the RF transistors connected in parallel and the switching pair in anti- parallel. The LO terms sum to zero and the IF signal doubled in the output. This configuration provides a high degree of LO-RF isolation, which alleviates filter requirements at the output.

Double Balanced mixers are less susceptible to noise than the single-balanced mixers because of the differential IF signal[14]. The input voltage in the IF frequency is amplified by the transconductance stage at the bottom of the circuit. The current is then steered to one side of the output or the other depending on the value of the LO. The result is a mixing of the LO and IF frequencies. The load stage used to convert mixed signal current into output RF

voltage, these resistors will influence the overall gain of the system and will be limited by remaining headroom voltage[15].

It is often that two factors affect linearity in the mixer circuit. First, if the applied signal at the driver stage is greater than the maximum differential input (also known as overdriving), the first compression will take place. Linearity can be improved in this situation by decreasing the driver stage transistor ratio (W/L), or increasing the bias current. The second, once the output load resistor size R is too large, the voltage drop V_{DS} across the switching transistors will decrease, forcing the switching transistors out of saturation and into the triode region of operation ($V_{DS} \leq V_{GS} - V_{TH}$). Reducing the size of the load resistors force the DC output voltage to a higher level, which make the gain lower.

However, three stacked transistors imply quite high supply voltage in the order of above 1.8 V and a strong LO voltage. This is a serious drawback of this architecture with respect to power consumption. But a reduction of the supply voltage leads to worse conversion gain and linearity performance.

Besides, the Gilbert mixer is based on the square-law characteristic of the MOS transistor in saturation. This characteristic restricts the linear range of the multiplier to small input voltage. The Gilbert cell has to be modified in order to cancel the quadratic terms originating from the basic MOS device for improving linearity and support low voltage operation[16]. Since in the conventional Gilbert Cell mixer, the IF input transistors operate in the saturation region and the LO transistors operate in the perfect switching situation.

Consequently, it appears that the mixer performance in terms of conversion gain and linearity can be simply improved by increasing the bias current of the driver stage. The IIP3 determines the maximum signal level that the mixer can handle a mixer with low NF and high IIP3 has larger dynamic range.

4.3 Performance Parameters

4.3.1 Conversion Gain

The conversion gain of a mixer is defined as the ratio of the desired IF output to the RF input. If the ratio is less than 1, it is referred as a conversion loss. Conversion gain is expressed in terms of voltage or power and it is usually given in dB:

$$\text{Power Gain (dB)} = 10 \log \text{ ———}$$

$$\text{Voltage Gain (dB)} = 20 \log \frac{V_L}{V_S} \frac{R_S}{R_L}$$

If input is matched, the relationship between power gain and voltage gain is given by:

$$\text{Power Gain (dB)} = \text{Voltage Gain (dB)} + 10 \log \frac{R_S}{R_L}$$

where R_S is the source resistance and R_L is the load resistance.

The conversion gain of a mixer is important because it affects the noise figure and linearity of the overall system by the loss. Moreover, the conversion gain of the mixer also determines the signal level at the output of the mixer, in which the signal will be fed into the following stages. Therefore, the conversion gain will affect the linearity performance of the system.

4.3.2 Gain Compression

A strong signal can saturate a mixer and reduce its gain. The input 1 dB compression point (P-1dB) measures the input power level that causes the mixer to depart from its linear magnitude response by 1 dB. Figure 4.3 shows the magnitude response of a mixer as a function of input signal power

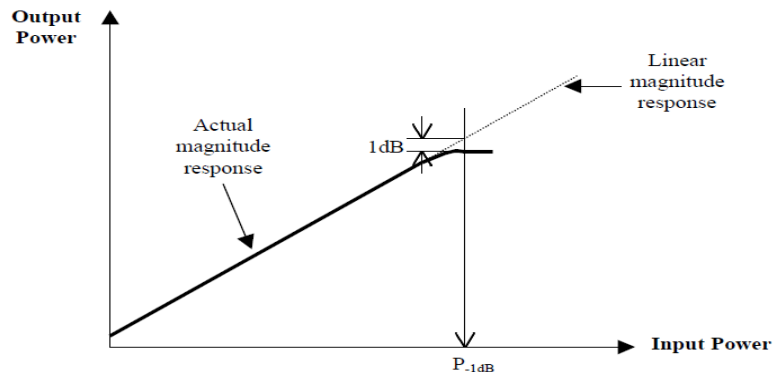


Figure 4. 3 Graphical representation of input 1dB Compression Point of Mixer

The dotted line shows the linear magnitude response of an ideal mixer. Due to odd-order nonlinearities and limiting such as voltage headroom limits the conversion gain of an actual mixer is compressed at high input power level. The actual output power is plotted with solid line. The point where the actual output power (solid line) is 1 dB lower than the ideal linear response (dotted line) is the input 1 dB compression point (P-1dB). If the gain compression is caused by limiting, the gain drops abruptly and the output power stays constant as the input power exceeds the input P-1dB. If the gain compression is caused by the odd-order nonlinearities, the gain decreases more gradually as the input power exceeds the input P-1dB.

At medium input power levels, gain compression is dominated by the third-order nonlinearity. If the input power continues to increase, higher-order non-linearities become significant.

4.3.3 Third order Intermodulation Distortion

The major function of a mixer is to perform frequency translation. Therefore it is inherently a non-linear circuit. However it is desirable for a mixer to behave very linearly with respect to all non-linearities except the one giving the desired frequency conversion. If we apply two tone input signal as follows

$$v_i = V_1 \cos \omega_1 t + V_2 \cos \omega_2 t$$

$$V_o = C_0 + C_1 + C_2 + C_3 + \dots \quad 4.1.1$$

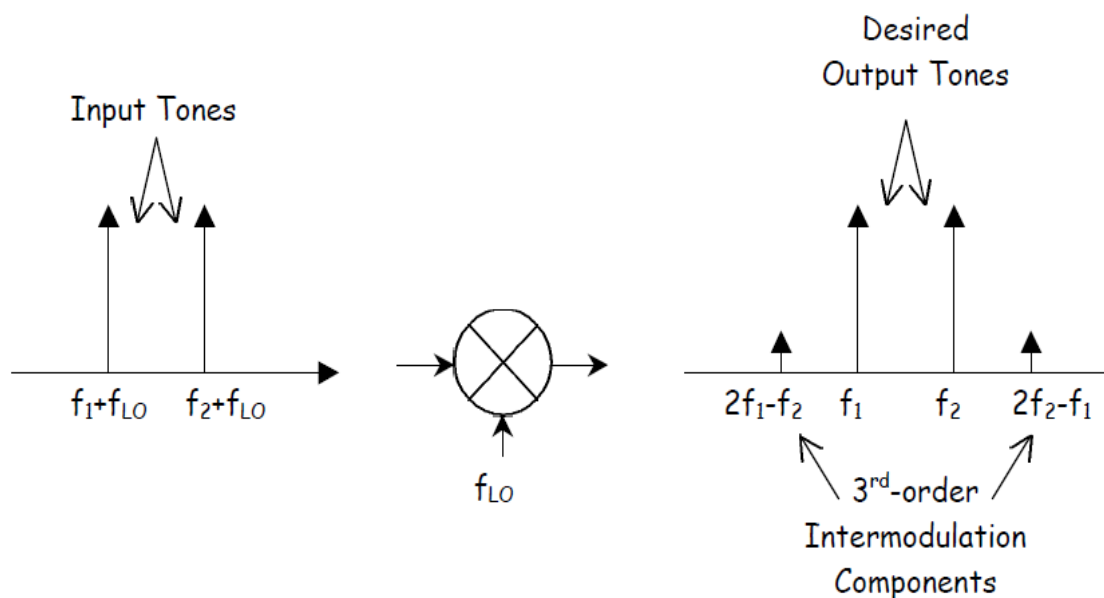


Figure 4. 4 Frequency spectrum at input and output port of Mixer

Figure 4.4 shows the frequency spectra at the input and output of a mixer including the 3rd-order intermodulation (IM3) components. When two tones are inputted to a mixer, distortion components at many different frequencies will be generated at the output of the mixer. Most of these distortion components are outside the desired signal band and can be filtered out along the receiver chain. However, some of these distortion components fall within the signal band and they cannot be filtered. If the two input tones are close in frequency, the third-order intermodulation components (IM3) will be closed to or lie inside the signal band.

The input third-order intercept point (IIP3) is used to characterize the linearity performance of the mixer. IIP3 is defined as the input power level where the 3rd order distortion product's power is equal to the power of desired output. The desired output comes from the first order term in equation (4.11). For 1dB increase in the input power, it results in a 1dB increase in the output power. The 3rd order distortion comes from the 3rd order term in equation (4.1.1). For 1dB increase in the input power, it results in 3 dB increase in the output distortion power. The graphical presentation of the input referred 3rd order intercept point is illustrated in Figure 4.5.

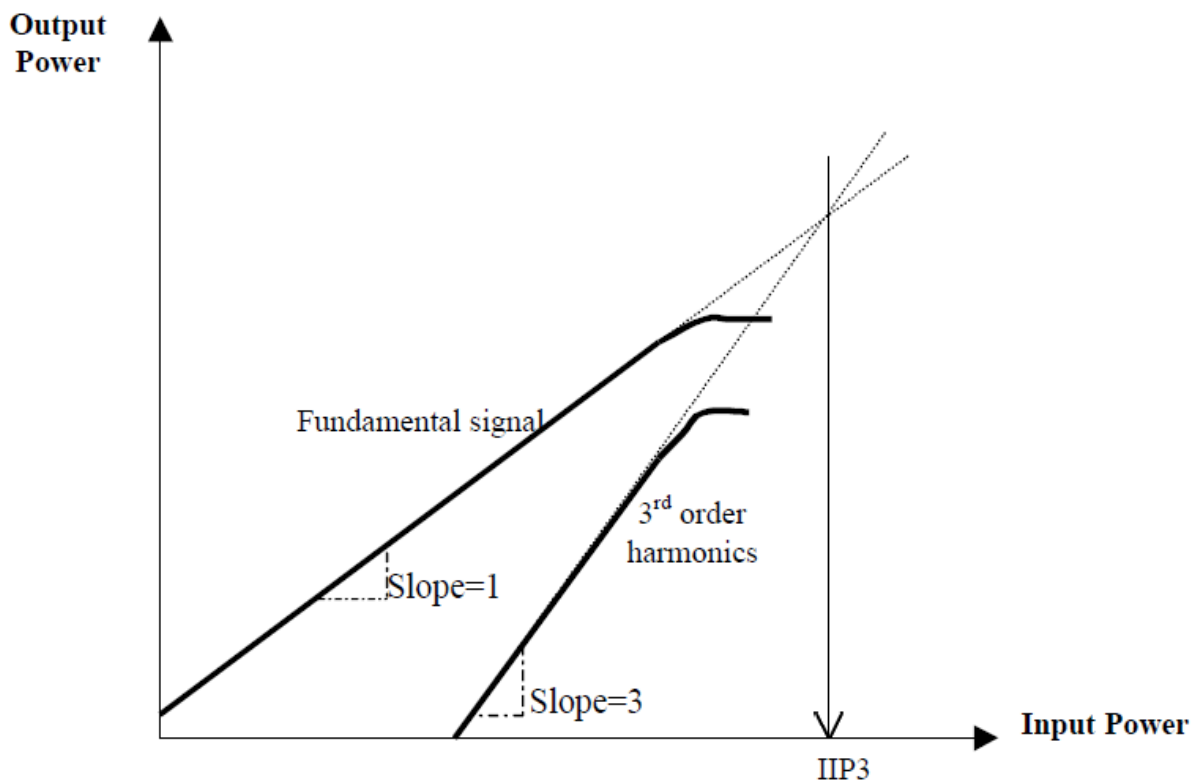


Figure 4. 5 Graphical representation of input third order intercept point IIP3

The curves in solid lines are the actual signal power observed at the frequency of interest and the dashed lines are the ideal behaviour of the first and the 3rd order terms of equation (4.1.1). When the input power is low, the curves of the actual signal power and ideal behaviour overlap. When the input power continues to increase, the curves of the actual signal power depart from their ideal behaviour lines, showing compressions from their ideal values. The compression is caused by the frequency components generated by the higher order terms in equation (4.1.1). These frequency components are the higher order distortion components. From Figure 4.5, IIP3 can be easily calculated

$$IIP3 = \sqrt{\frac{P_{out1} + P_{out3}}{P_{in}}}$$

where P_{out1} and P_{out3} are the measured output power of the desired signal and the 3rd order distortion respectively and P_{in} is the input power.

4.4 Proposed up conversion mixer for High Linearity

A Schematic of proposed up conversion mixer is shown in Figure 4.6. This Schematic consists of modified Gilbert type mixer with Pre-filter. There are three ports in this mixer setup. These three ports are for IF frequency, LO frequency and Output. The main purpose of the Pre-filter after the mixer is to suppress the Intermodulation Products before they are amplified by power Amplifier. The Pre-filter consists of passive LC circuit. The proposed Mixer is a High Performance Up Conversion Mixer for Zigbee Transmitter because of its good linearity performance[17].

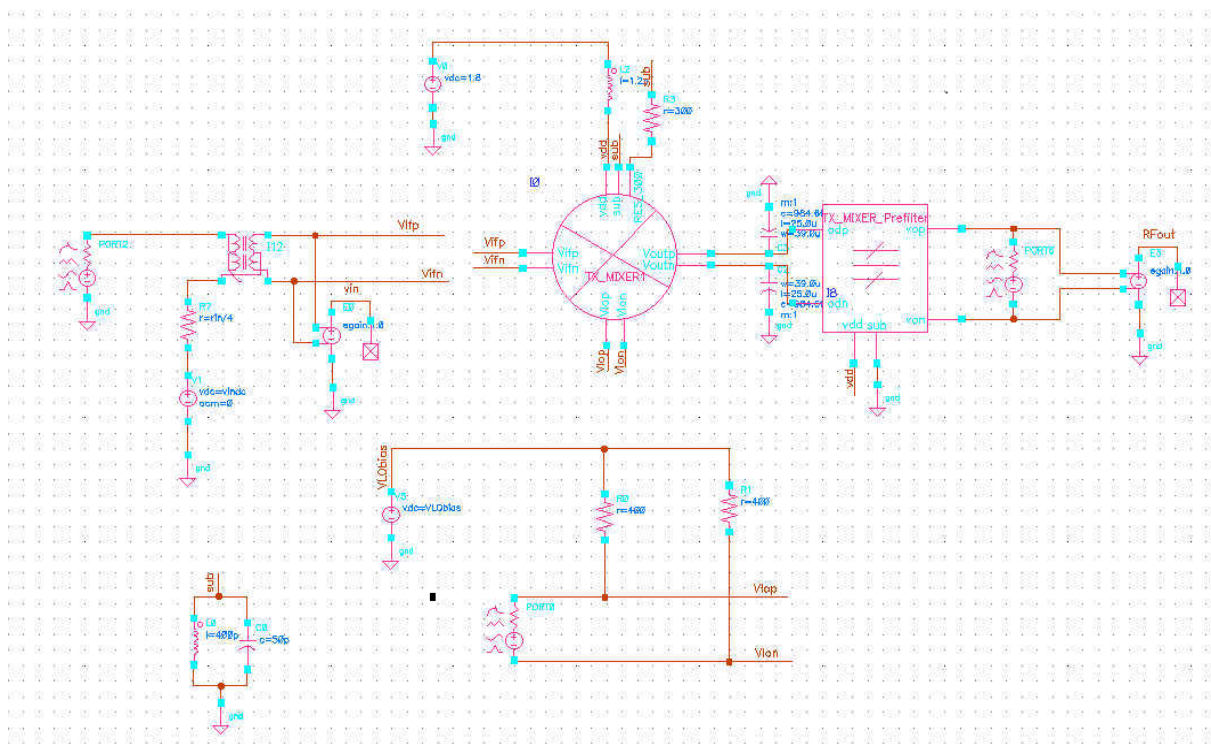


Figure 4. 6 Schematic of proposed Up Conversion Mixer setup

The IF input signal is provided by an ideal balun driven by port element connected having a characteristic impedance of 1Ω Ohm. The LO signal is provided by another port element and is directly coupled to the mixer inputs [18]. This mixer does not have an internal LO bias and therefore LO DC bias is provided by an external source as shown in the Figure 4.6. The output of the mixer is converted to the pre-filter as described above. The output of the filter is

connected to a port element having 50Ω Ohm characteristic impedance. The output is also converted to a single-ended output by a vcvs (Voltage-Controlled Voltage Source) element. The mixer is characterized at the block level. Therefore, it is important to include other circuit elements to represent parasitic associated with the top-level chip, package, and printed circuit board (PCB) substrate interconnect. If models for these interconnect elements are not available then estimated models can be implemented using lumped elements as is done here.

4.4.1 Circuit Operation

The baseband (IF) inputs first feed into a pair of level shifting devices followed by the transconducting pair of transistors PM0 and PM3 in Figure 4.7

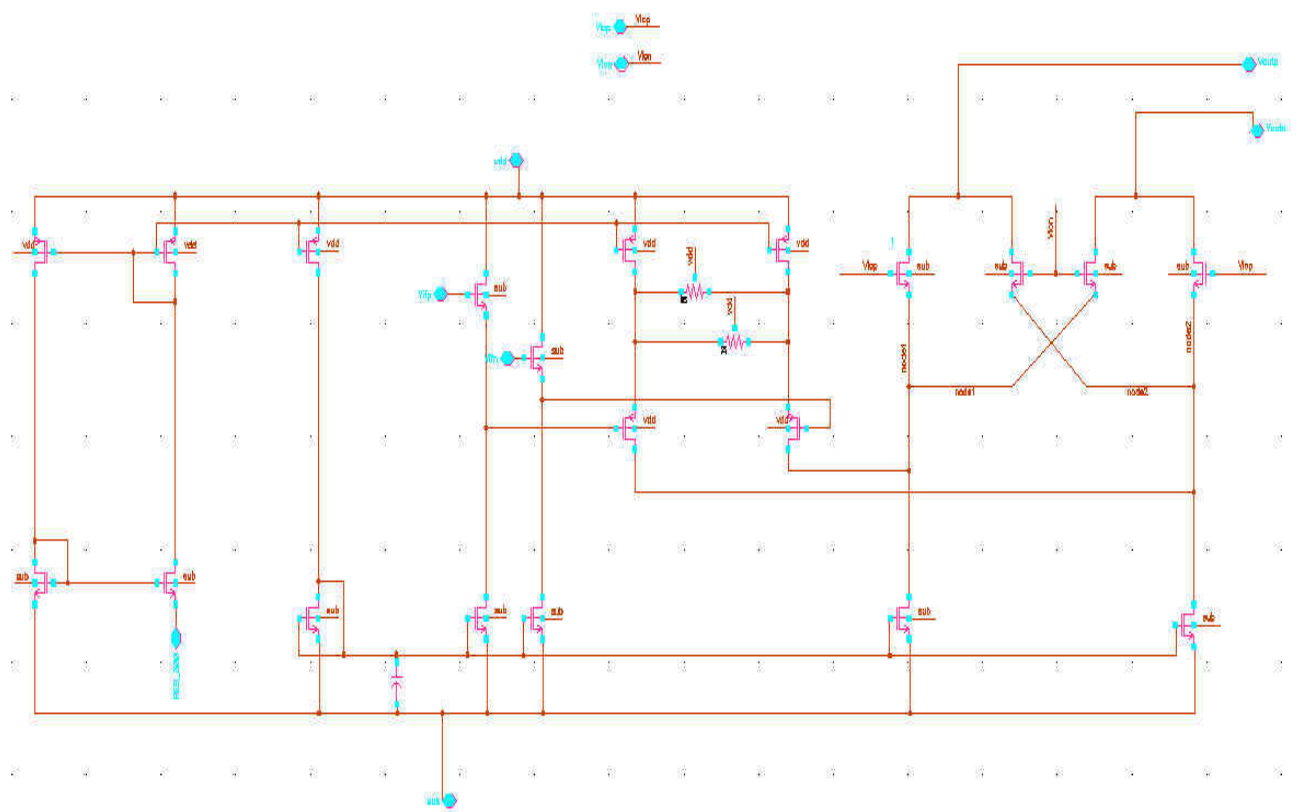


Figure 4. 7 Schematic of Proposed Up Conversion Mixer

For correct linear operation, these devices should not be driven into saturation and therefore should be operated with signals well below their 1dB compression point. The current output signals are then folded into a Gilbert cell double balanced mixer core formed by transistors NM7-NM10 as shown in Figure 4.7. These transistors multiply the baseband currents with the LO signal to produce the RF signal which consists of 2 side-bands (FLO-FBB, FLO+FBB). The differential mixer outputs are left as open drains so that the currents from both the I and Q mixers can be summed in the subsequent Tx pre-filter stage. As a

consequence of the quadrature LO drive and the summation process the upper sideband RF products will add constructively while the lower sideband products are suppressed

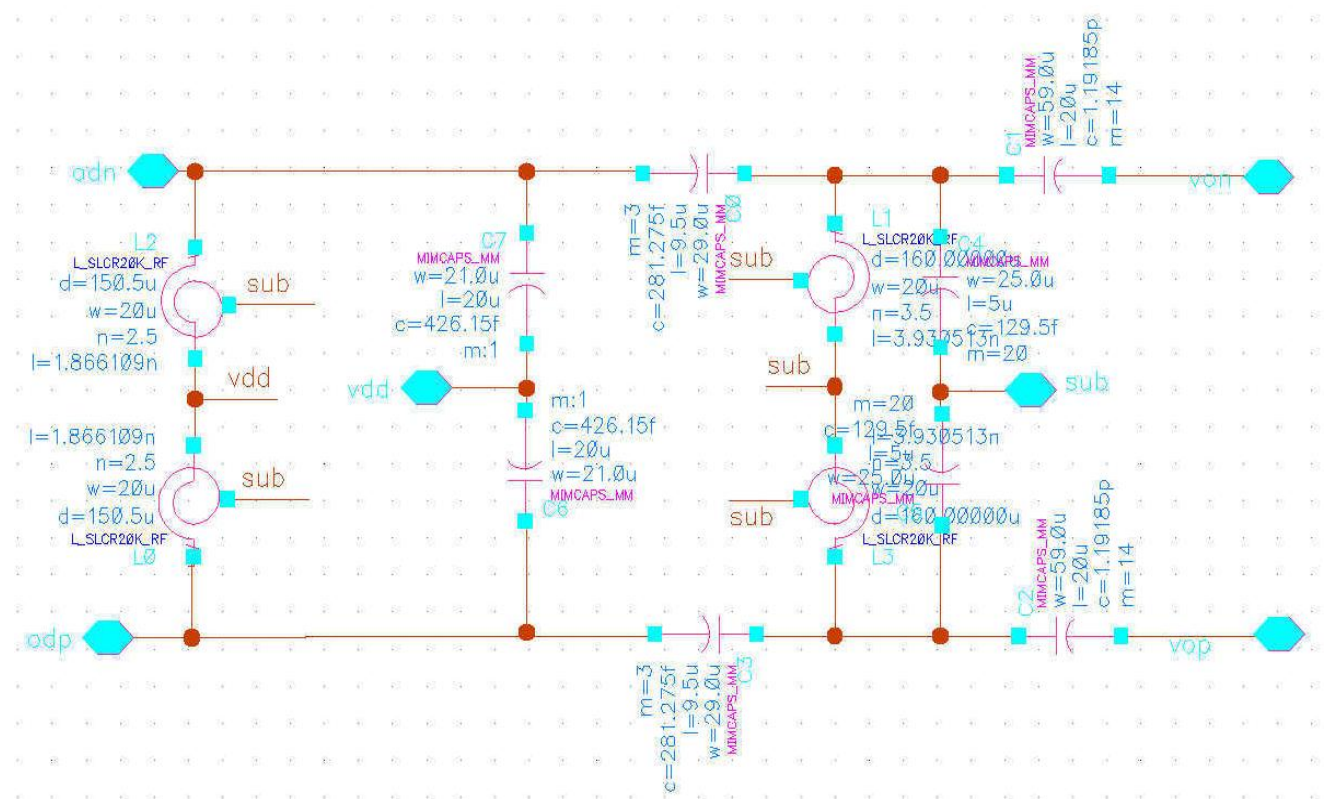


Figure 4. 8 Schematic of Pre-filter

The pre-filter shown in Figure 4.8 consists of a passive LC-circuit. In addition to being the output load for both mixers forming the I/Q modulator it helps to suppress the higher order modulation products before they are amplified by the power amplifier [19].

4.5 Results and Discussion

The mixer circuit is simulated in Cadence© using SpectreRF simulator in UMC-0.18um Mixed Signal CMOS RF models. The mixer is designed to operate at 1.8V voltage supply. Frequencies of three ports in the mixer are specified at IF Frequency of 5 MHz, LO frequency of 2.45 GHz and RF frequency of 2.45GHz respectively.

A mixer’s frequency conversion is characterized by conversion gain. The *voltage conversion gain* is the ratio of the RMS voltages of the RF and IF signals. The conversion gain is measured to be -11.3dB. Chosen PAC and PSS analysis for simulating Conversion Gain and IIP3.

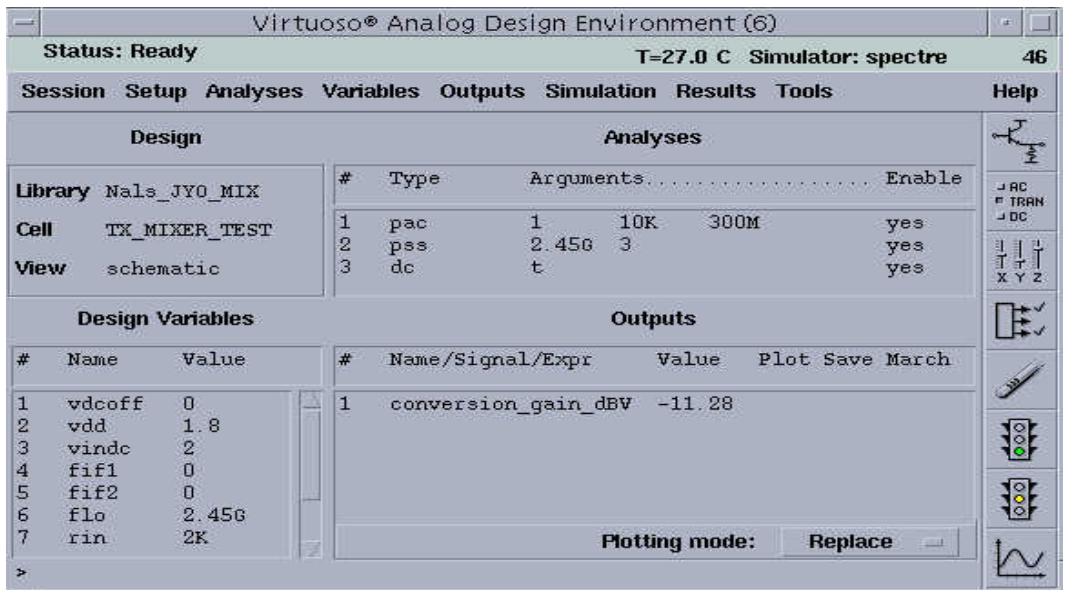


Figure 4.9 Analog Design Environment for Conversion Gain

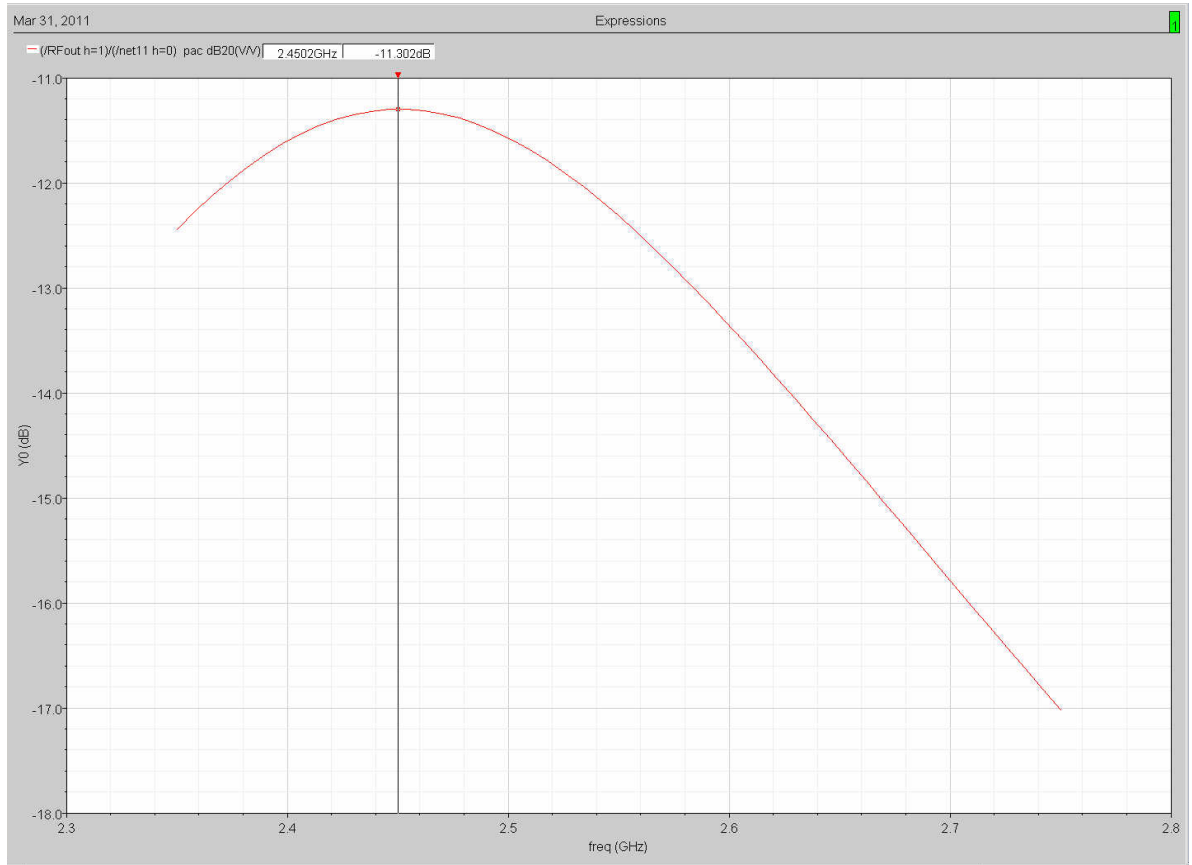


Figure 4.10 Conversion Gain of the Proposed Mixer

The linearity performance is measured using two-tone test. A second input signal is input to the RF ports of the mixer. The RF signal frequency is at 1.9GHz, and the second input signal frequency is at 1.901GHz. IIP3 is the extrapolated intercept point between fundamental term

and the third order intermodulation term. Figure 4.11 shows the simulation result of both fundamental output power and the third-order intermodulation distortion power as a function of input power. 5dBm IIP3 is measured with a RF input power of -25dBm

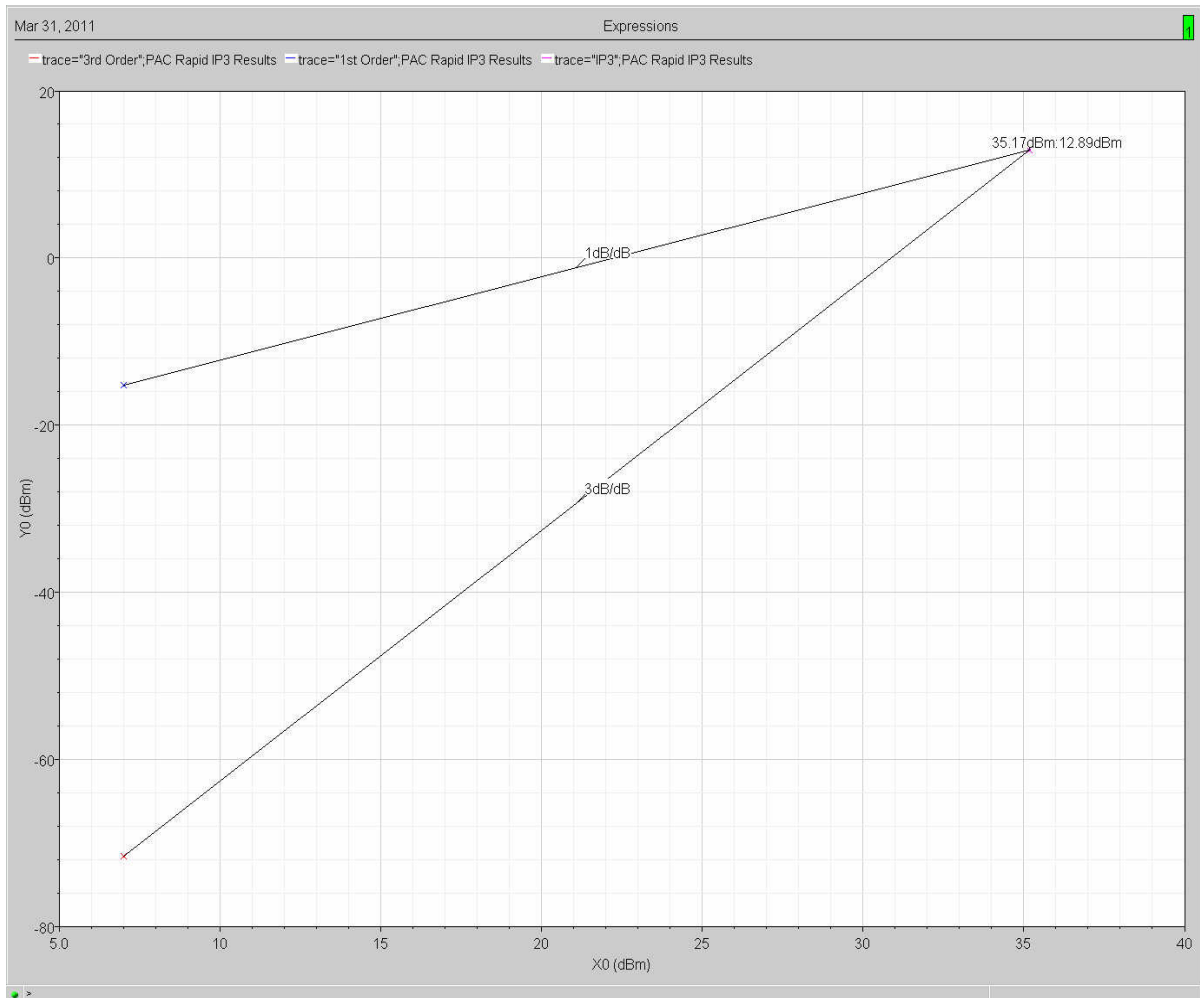


Figure 4. 11 IIP3 and OIP3 of the Proposed Mixer

Figures 4.10, 4.11 show simulation results of the mixer. It is found that the mixer achieves a conversion gain of -11.30 dB , an IIP3 of 35.16dBm , and OIP3 of 12.88dBm while keep a power consumption as low as possible.

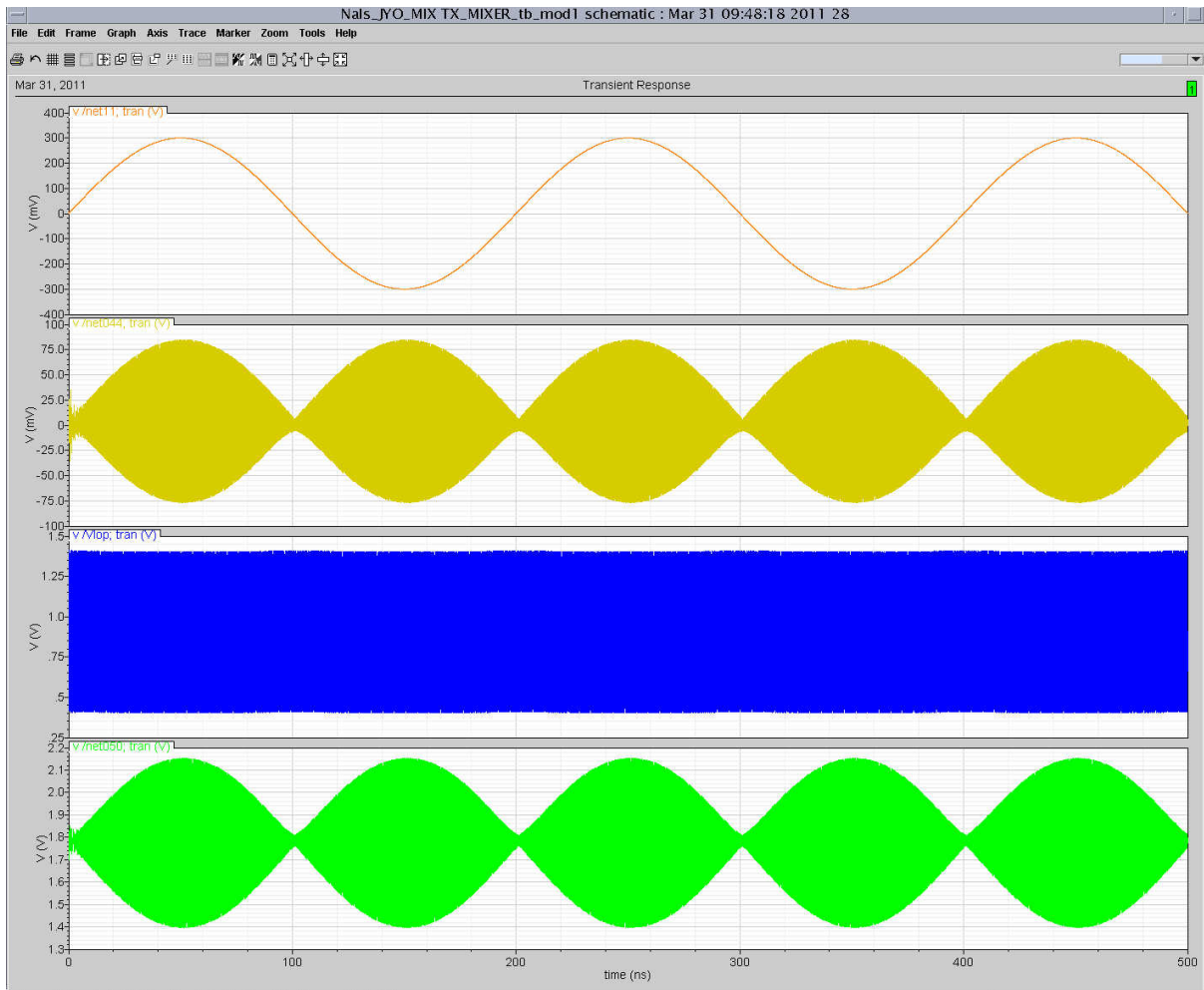


Figure 4. 12 Transient Voltage of Input IF, LO, Pre-filter Output, Output of the mixer

Table 4.1 summarizes the simulation results of the proposed up conversion Mixer. The proposed Up conversion mixer represents excellent property of the linearity.

The simulation and measurement results are summarized in Table 4.1

Table 4. 1 Summary of linearity improved mixer performance

Parameters	Values
Operating Frequency[GHz]	2.45
Supply Voltage [V]	1.8
Current dissipation[mA]	10
Conversion Gain [dB]	-11.3
IIP3[dBm]	35.16
OIP3[dBm]	12.88
Technology	0.18 CMOS

Chapter-5

Design of a Power Amplifier

5.1 Introduction

Power Amplifiers (PAs) are key components in the wireless communications industry, TV transmissions, Radar, and RF heating which consume a great amount of power in overall transceiver. The PAs must achieve high operation efficiency in order to maximize the battery life and minimize the size and cost. The general PA design focuses on the whole system architecture and should achieve advantages in terms of performance, cost, and size. To allow full system integration and low costs, CMOS technology is well suited. To achieve a high linearity, class-A power amplifiers are preferred.

Many efforts have been made on RF block integration using CMOS technology. But, it is still a big challenge for CMOS PA to be competitive with the PAs made of compound semi-conductor, the power amplifier is regarded as the last key area to be solved for the single chip solution. There are two main issues in the design of PAs in CMOS process, namely, gate oxide breakdown and hot carrier effects, which restrict the output power. Moreover, both problems get worse as the technology scales. For the PA based WLAN standards, the linearity is a key parameter which is closely related to the power consumption and distortion.

In an implantable system, the power consumption needs to be reduced to the minimum possible limit such that the battery needs not be charged repeatedly. Since the power amplifier is the unit that consumes most of the transmitter's power an efficient PA is needed to achieve the required level of low power consumption. The Modulation scheme used in ZigBee is OQPSK modulation. It is a variant of QPSK modulation formed by staggering the inphase and quadrature components of QPSK by half a symbol period thus the maximum allowed phase shift is 90° . When OQPSK is band limited, the resulting intersymbol interference (ISI) will cause the envelope to droop slightly in the region of a $\pm 90^\circ$ transition instead of being constant envelope. This will increase spectral regrowth and out of band emission. To avoid these problems linear classes of PA, Class A Power Amplifier had been used with ZigBee transmitters

5.2 RF Power Amplifier Classification

Class of amplifier operation differ not in only the method of operation and efficiency, but also in their power-output capability. The power-output capability is defined as output power per transistor normalized for peak drain voltage and current of 1V and 1A, respectively. In general, RF power Amplifier can be defined by two: Linear amplifier and nonlinear amplifier. Linear amplifiers attempt to preserve the original wave shape of the input signal into the output signal. The main classes of linear amplifier are: Class A, Class B, Class AB.

Nonlinear amplifier can't attempt to preserve the original wave shape of the input signal at the output, but it can perform a better power efficiency. The main classes of nonlinear amplifier are: Class C, Class E, Class F and some other Class G, Class H, and Class S.

5.2.1 Class A Power Amplifier

Class A amplifier is the simplest power amplifier type in terms of design and construction. The Class A amplifier has a conduction angle of 360° . Conduction angle refers to the time period for which a device is conducting. Thus a conduction angle of 360° tell us that in Class A operation the device conducts current for the entire input cycle. Class A amplifier are considered to be the most linear since the transistor is biased in the centre of the load line to allow for maximum voltage and current swings without cut-off saturation

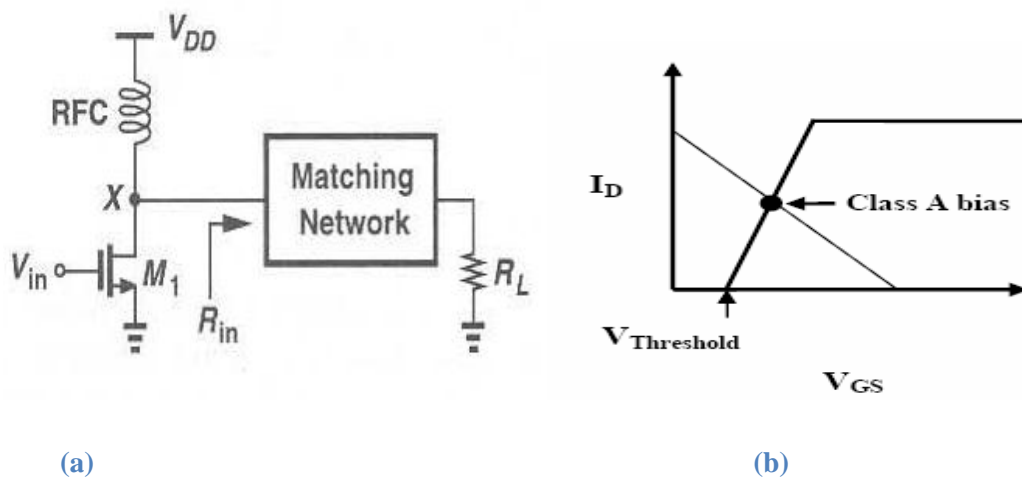


Figure 5. 1 (a) Class A Power Amplifier, (b) Biasing for Class A Power Amplifier

Radio Frequency Choke represents a large inductor which makes the supply voltage to be lowered by a factor of two because V_X can swing from approximately 0 to $2V_{DD}$.

How, the quiescent current is large enough that the transistor remains at all times in the active region and acts as a current source, controlled by the drive. As a result, it can be shown that the maximum efficiency achievable from a Class A power amplifier is only 50%. And this is a theoretical number and the actual efficiency is typically much less.

The maximum ac output voltage V_{om} is slightly less than V_{DD} and the maximum ac output current I_{om} is equal to I_{dq} in Class A amplifier. In the inductor-less system, the output voltage V_{om} will not be able to rise above the supply voltage, therefore, the swing will be constrained to $V_{DD}/2$ and not V_{DD} . The drain voltage must have a dc component equal to that of the supply voltage and a fundamental-frequency component equal to that of the output voltage; hence

$$V_D = V_{DD} + V_{om} \sin\theta$$

The dc Power $P_{dc} = V_{DD} \cdot I_{dq}$

The maximum output power is

$$P_o = - V_{om} I_{om} - V_{DD} \cdot I_{dq}$$

And the efficiency is

$$\frac{P_o}{P_{dc}} \cdot 100 = \frac{- V_{om} I_{om} - V_{DD} \cdot I_{dq}}{V_{DD} \cdot I_{dq}} \cdot 100 \leq 50 \%$$

The difference between the dc power and output power is called power dissipation

$$P_d = P_{dc} - P_o$$

5.2.2 Class B Power Amplifier

This is an amplifier in which the conduction angle for the transistor is approximately 180° . The gate bias in class B is set at the threshold voltage point of the transistor. Hence there is a current flowing at the output of the device only when there is a signal at the input. Moreover the device would conduct current only when the input signal level is greater than the threshold voltage.

The class-B amplifier operates ideally at zero quiescent current, so that the dc power is small. Therefore, its efficiency is higher than that of the class-A amplifier. The price paid for the enhancement in the efficiency is in the linearity of the device.

Common configuration of Class-B amplifier is push-pull amplifier as shown in Figure 5.2. In this configuration one transistor conducts during positive half cycles of the input

signal and the second transistor conducts during the negative half cycle. In this way the entire input signal is reproduced at the output.

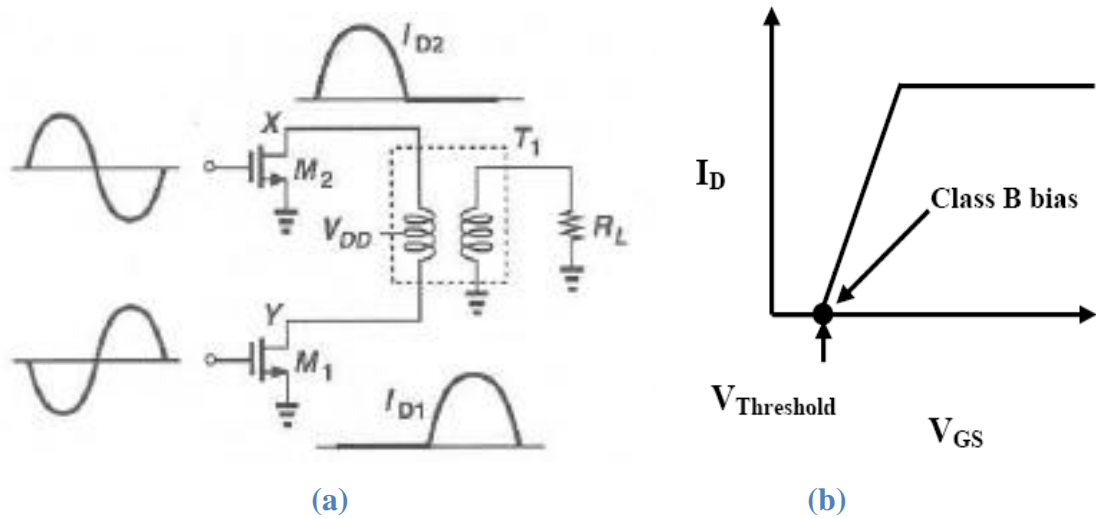


Figure 5. 2 (a) Class B stage using Transformer, (b) Biasing for Class B amplifier

Due to this behaviour; there is a large saving in the power loss. It can be shown that the maximum theoretical efficiency achievable with Class B operation is about 78%.

The output power for the single-ended class-B amplifier is

$$P_o = -I_{om} V_o$$

the dc drain current is

$$I_{dc} = 2 \text{ ---}$$

the dc power is

$$P_{dc} = 2 \text{ ---}$$

and the maximum efficiency when $V_{om} = V_{DD}$ is

$$\text{---} = \text{---} \cdot 100 \leq 78.5\%$$

5.2.3 Class AB Power Amplifier

The crossover distortion effect in Class B amplifier can be minimized by biasing the gate in such a way so as to produce a small quiescent drain current. This leads to the type of amplifier called Class AB, where the transistor is biased above the threshold voltage but below the centre of the load line. Class AB amplifier operation, as the name suggests, can be considered being a compromise between Class A and Class B operation. The conduction angle of a class AB amplifier lies between 180° and 360° . By varying the conduction angle

the amplifier can be made to behave more as a Class A or Class B amplifier; hence the theoretical maximum efficiency of a Class AB amplifier 50° and 78.5° .

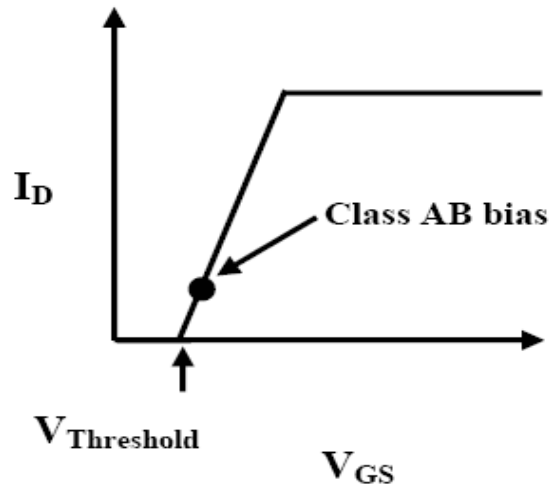


Figure 5. 3 Biasing for Class AB amplifier

But commercial Class AB amplifiers typically much lower efficiency in the order of 40-55%. Thus a trade-off between linearity and efficiency can be achieved by simply changing the gate bias. Class AB amplifier can also be realized in push-pull configurations even though single transistor configuration is preferred for high frequency linear operation.

5.2.4 Class C Power Amplifier

A Class C power amplifier is a non-linear power amplifier used in places where linearity is not a requirement and high efficiency is highly desired. Class C amplifiers are widely used in constant envelope modulation systems where linearity is not required. The transistor is biased below threshold for Class C operation and hence the device conduction angle varies from 0° and 180° .

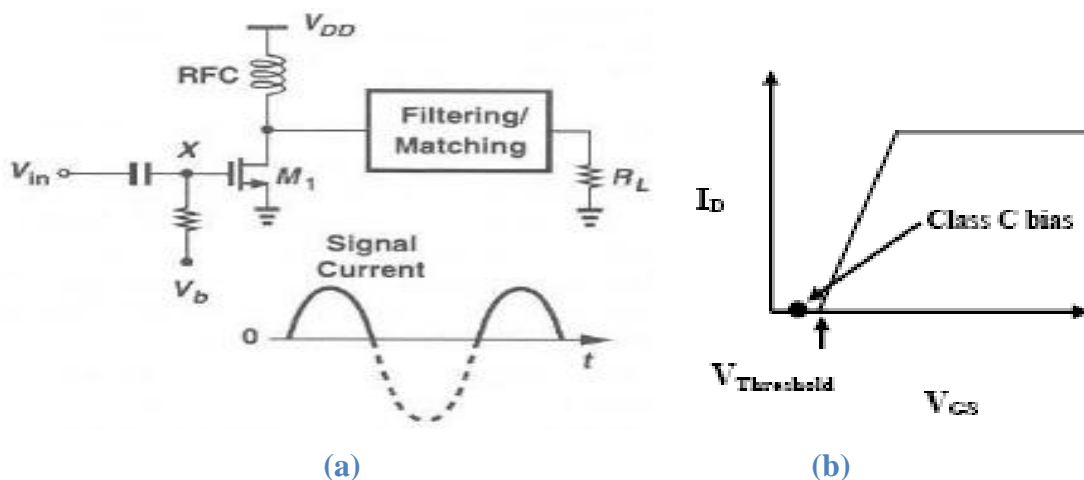


Figure 5. 4 (a) Class C stage , (b) Biasing for Class C amplifier

As shown in Figure 5.4 (a), the circuit is biased such that M_1 turns on if $V_{in} = |V_b| + V_{TH}$, where V_b is the negative voltage. In other words the transistor stimulates the output with a narrow current waveform in each cycle. The matching circuit usually includes some filtering to suppress the harmonics.

The distinction between Class C and one transistor Class B stages is in conduction angle θ . As θ decreases, the transistor on for a small fraction of the period, thus dissipating less power. For the same reason, however the power delivered to the load also decreases. If the current drawn by the transistor is assumed to be a piece of sinusoid and output voltage is a sinusoid with a peak voltage equals to V_{DD} , then the efficiency can be calculated as a function of θ . The Efficiency is given by

$$\eta = \frac{P_{out}}{P_{in}}$$

varying from 50% for $\theta = 360^\circ$ (class A) to 79% for $\theta = 180^\circ$ (class B) to 100% for $\theta = 0$ (class C).

The maximum efficiency of 100% is often considered as a prominent feature of class C stages. However another attribute that must also be taken into account is the actual power delivered to the load. The output Power is given as

$$P_{out} = \frac{1}{2} V_{DD} I_{out}$$

This quantity drops to zero as the conduction angle vanishes. In other word Class C exhibits a high efficiency only if it delivers a fraction of peak output power. For this reason, true Class C is not suited to the transceivers, where efficiency at full output power is of greatest concern.

5.2.5 Class D Power Amplifier

The voltage mode Class D amplifier is defined as a switching circuit that results in the generation of a half-sinusoidal current waveform and a square voltage waveform. Class-D PAs as shown in Figure 5.5(a) use two or more transistors as switches to generate a square drain-voltage waveform. A series-tuned output filter passes only the fundamental-frequency component to the load, Class-D amplifiers suffer from a number of problems that make them difficult to realize, especially at high frequencies. First, the availability of suitable devices for the upper switch is limited. Secondly, device parasitics such as drain-source capacitance and

lead inductance result in losses in each cycle. If realized, (they are common at low RF and audio frequencies).

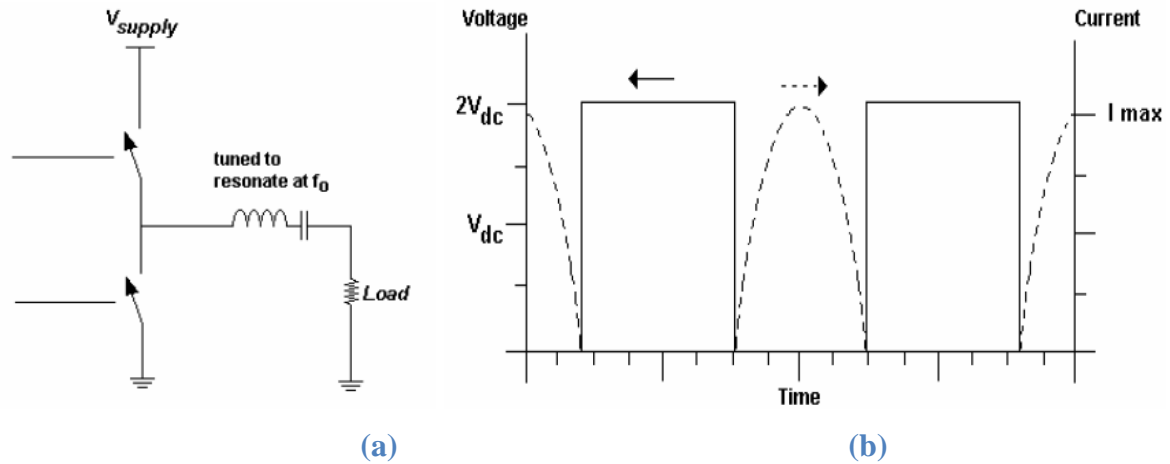


Figure 5. 5 (a) Class D stage, (b) Class D voltage and Current Waveforms

Class-D amplifiers theoretically can reach 100% efficiency, as there is no period during a cycle where the voltage and current waveforms overlap (current is drawn only through the transistor that is on) as shown in Figure 5.5(b).

5.2.6 Class E Power Amplifier

Class E power amplifiers are fundamentally different from the other types of power amplifiers discussed before. In the previously described power amplifier classes, it was seen that the operational differences were obtained by the selection of the bias point. However, in a Class E amplifier as shown in Figure 5.6 (a), only circuit-independent signal guidelines are given, and the topology is not as restricted.

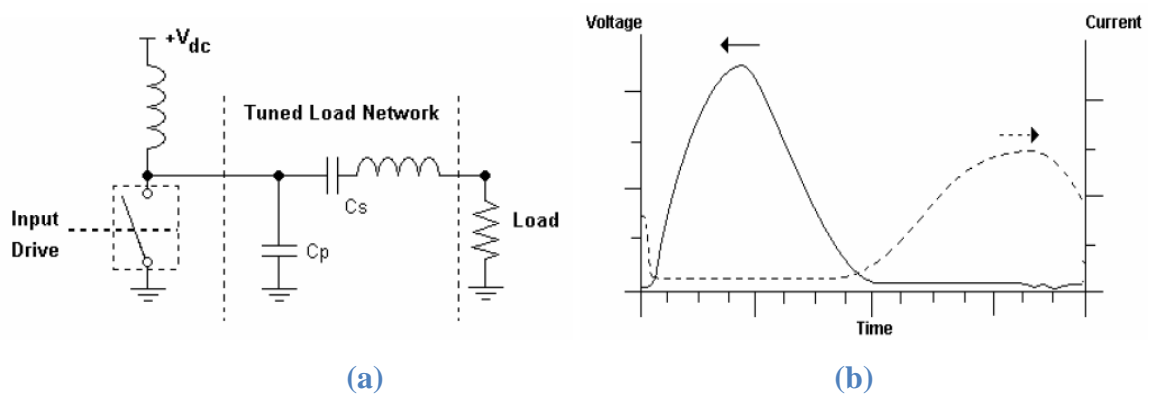


Figure 5. 6 (a) Class E stage , (b) Class E voltage and Current Waveforms

The idea behind the Class E amplifier is to have non-overlapping output voltage and output current waveforms as shown in Figure 5.6 (b), and to limit the values of the voltage, current, and the derivative of the voltage with respect to time at the instants when the transition between non-zero currents and non-zero voltage occurs.

For Class E amplifier operation, the transistor acts like a switch. Also the terms “on” state and “off” state are used to describe the time period when the transistor starts conducting and stops conducting respectively. The voltage across the switch must return to zero just before the switch turns “on” and starts conducting current. Similarly the current through the switch must return to zero just before the switch turns “off”. These two conditions avoid the energy dissipation caused by the simultaneous superposition of substantial voltage and current on the switching transistor during transition from “on” to “off” state or “off” to “on” state. Another condition for Class E operation is that the voltage across the switch must return to zero with zero slope (i.e., $di/dt = 0$) and the voltage across the transistor at the beginning of “on” state is zero. Hence for deviation in the switching instant from the ideal switching time the corresponding output voltage or current will be very small, and the power lost in the device due to this non-ideal will be relatively small. With all these conditions satisfied, very high efficiencies can be achieved. The maximum theoretical efficiency of Class E amplifier is 100%.

5.2.7 Class F Power Amplifier

Class-F power amplifiers are usually considered as very high efficiency (80% or more Power-Added Efficiency) amplifiers where the high efficiency is obtained through the use of harmonic traps (L-C filters or quarter-wavelength transmission lines) which provide suitable terminations (either open or short) for the harmonics generated.

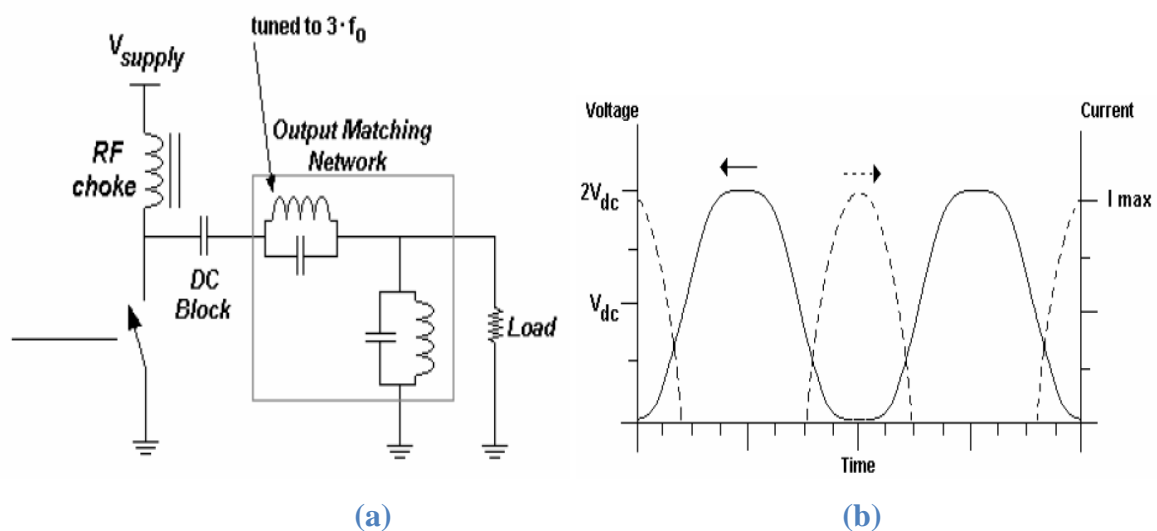


Figure 5.7 (a) Class F stage , (b) Class F voltage and Current Waveforms

By doing this, square wave drain voltage and a peaked half-sinusoidal drain current out of phase by 180% are produced. Since only a drain voltage or a drain current exists at any given time, the power dissipation is ideally zero resulting in 100% theoretical efficiency. These

very high efficiency values are usually associated with poor linearity. However the linearity can be improved to meet the design standards but compromising on efficiency.

5.3 Performance Parameters

Linear modulation techniques are bandwidth efficient and hence are very attractive for use in wireless communication systems where there is an increasing demand to accommodate more and more users within a limited spectrum. While linear modulation schemes have very good spectral efficiency, they must be transmitted using linear RF amplifiers which have poor power efficiency. Using power efficient nonlinear amplifiers leads to the regeneration of filtered sidelobes which can cause severe adjacent channel interference, and results in the loss of all the spectral efficiency gained by linear modulation. However, clever ways have been developed to get around these difficulties. The most popular linear modulation technique, OQPSK is used in Zigbee Transmitter.

The RF power amplifier (PA), an important element in transmitter units of communication systems, is expected to provide a suitable output power at a very good gain with high efficiency. The output power from a PA must be sufficient for reliable transmission. High gain can reduce the number of amplifier stages required to deliver the expected output power and hence reduces the size and manufacturing cost. High efficiency improves thermal management, battery lifetime and operational costs. Good linearity is necessary for bandwidth efficient modulation. However these are contrasting requirements and a typical of power amplifier which differ from each other in terms of linearity, output power efficiency. This thesis will present a class A PA design.

5.3.1 Power Added Efficiency

Power Added Efficiency (PAE) incorporates the RF drive power by subtracting it from the output ; PAE gives a reasonable indication of Power amplifier performance. The equation of

$$PAE = \frac{P_{out} - P_{drive}}{P_{DC}}$$

The Power Amplifier's Efficiency is a measure of its ability to convert the DC power of the supply into the signal power delivered to the load.

$$\eta = \frac{P_{out}}{P_{DC}}$$

5.3.2 Power Gain

The Power Gain of a electrical network is the ratio of input power to the output power. Three important Power gain are operating power gain, transducer power gain, and available power gain.

5.3.2.1 Operating Power Gain

The operating power gain of a two-port network, G_P , is defined as:

$$G_P = \frac{P_{\text{load}}}{P_{\text{input}}}$$

where

P_{load} is the maximum power delivered to the load

P_{input} is the average power entering the network

5.3.2.2 Transducer Power Gain

The transducer power gain of a two-port network, G_T , is defined as:

$$G_T = \frac{P_{\text{load}}}{P_{\text{source,max}}}$$

where

P_{load} is the average power delivered to the load

$P_{\text{source,max}}$ is the maximum available average power at the source

5.3.2.3 Available Power Gain

The available power gain of a two-port network, G_A , is defined as:

$$G_A = \frac{P_{\text{load,max}}}{P_{\text{source,max}}}$$

where

$P_{\text{load,max}}$ is the maximum available average power at the load

$P_{\text{source,max}}$ is the maximum power available from the source

Similarly $P_{\text{load,max}}$ may only obtained when the load impedance is the complex conjugate of the output impedance of the network.

5.3.3 One dB Compression Point

The one dB compression point (P_{1dB}) indicates the power level that causes the gain to drop by 1 dB from its small signal value. The gain is constant for a given frequency when a power amplifier is operated in its linear region. However when the input signal power is kept increased, there is a certain point beyond which the gain is seen to decrease, the input 1-dB compression point is defined as the power level for which the input signal is amplifier 1dB less than the linear gain.

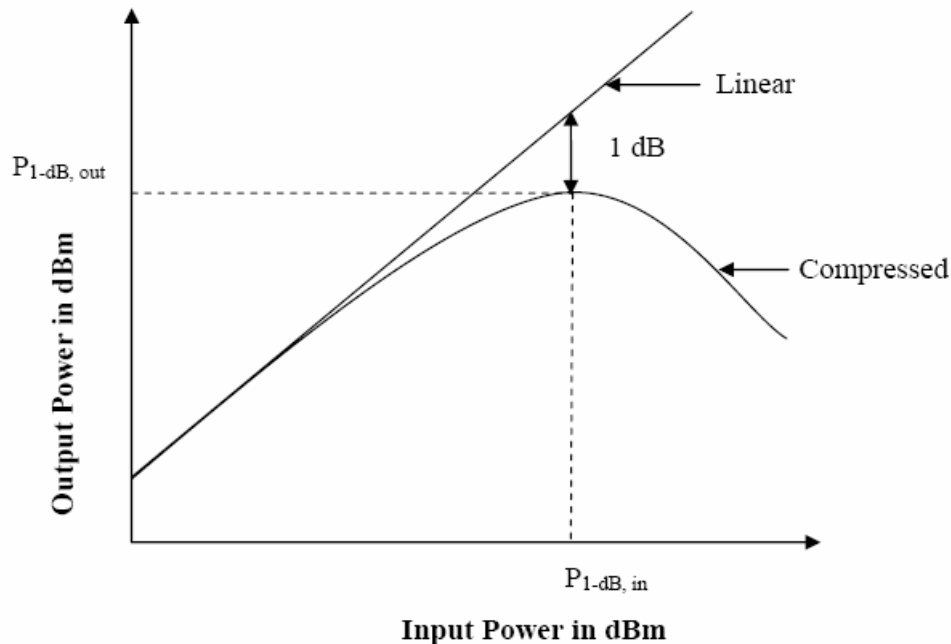


Figure 5. 8 Gain Compression Plot

5.4 Impedance Matching Network

Matching networks provide a transformation of impedance to a desired value to maximize the power dissipated by a load. For example, the Figure 5.9 below illustrates the matching networks for a transistor amplifier. The matching networks ensure that the proper impedance is seen by the amplifier. One such matching method may be a conjugate match of the impedance.

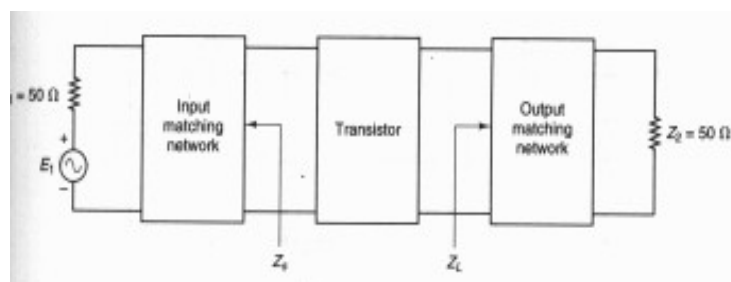


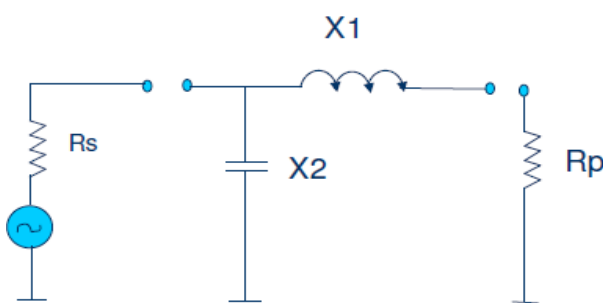
Figure 5. 9 Block Diagram of Amplifier with matching networks

There are many useful matching networks including the following

- L Section matching network
- T Section matching network
- Section matching network

5.4.1 L Section Matching Network

By using capacitors and inductances we can achieve impedance matching without power loss assuming the components are ideal. Real capacitors and inductors exhibit losses which need to be minimized during the match design. The most critical component is the inductor. At high frequencies the skin effect and inter winding capacitance decrease the quality of the coil.



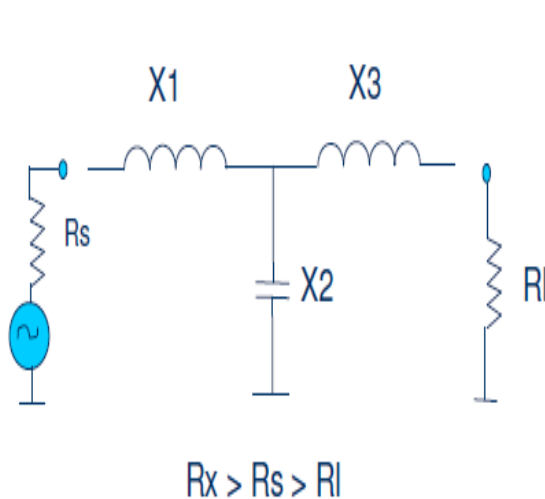
$$X1 := \sqrt{(Rs \cdot Rp) - Rp^2}$$

$$X2 := Rs \cdot \frac{Rp}{X1}$$

$$Rs > Rp$$

Figure 5. 10 L Section matching network

5.4.2 T Section Matching Network



$$Q := \sqrt{\left(\frac{Rx}{Rl}\right) - 1}$$

$$X3 := Rl \cdot Q$$

$$X2 := -Rl \cdot \frac{(1 + Q^2)}{\left[Q + \sqrt{\left[Rl \cdot \frac{(1 + Q^2)}{Rs} \right] - 1} \right]}$$

$$X1 := Rs \cdot \sqrt{\left[Rl \cdot \frac{(1 + Q^2)}{Rs} \right] - 1}$$

$$Rx > Rs > Rl$$

Figure 5. 11 T Section matching network

5.4.3 π Section Matching Network

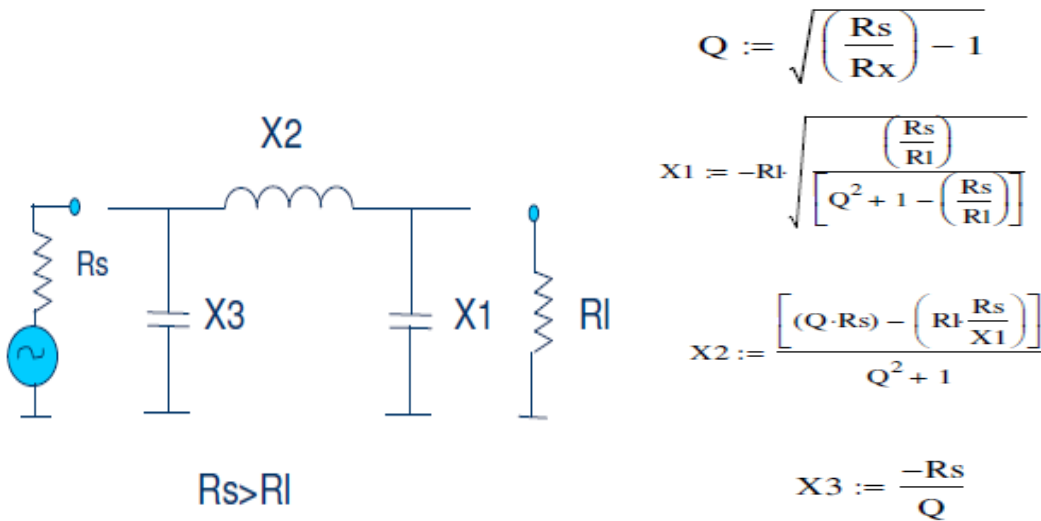


Figure 5. 12 π Section matching network

5.5 Proposed Differential Class A Power Amplifier

With the improvement of the submicron CMOS process, threshold voltage and oxide breakdown voltage decreases. There are two main issues in the design of power amplifiers in the submicron CMOS: oxide breakdown and hot carrier effect. The oxide breakdown sets a limit on the maximum signal swing of the drain electrode. The hot carrier effect increases the threshold voltage and degrades the performance of the device [20]. The recommended voltage is 5%-10% above the maximum allowed supply voltage to avoid the hot carrier effect and extend the product lifetime. But this introduces the oxide breakdown problem. The supply voltage has been limited by these two issues. Designing a power amplifier at a smaller supply voltage has several drawbacks. According to the equation 5.1, the impedance at the output must be reduced by the square value of supply reduction, in order to get the same output power at the lower bias voltage.

$$R_o = \frac{V^2}{2 \cdot P_o} \dots\dots\dots (5.1)$$

With the output impedance decreasing, the output current becomes larger by the inverse of the supply reduction. This increases the loss in the parasitic resistors of the matching network and the transistor. A larger transistor is required to handle the larger current which in turn increases the parasitic capacitances. This reduces the input impedance, making the input matching more difficult. Overall, the gain and efficiency are reduced as a result of reduced supply voltage.

Cascode configuration and thick-oxide transistors [21, 22] have been used to eliminate the effects of oxide breakdown and the hot carrier degradation, allowing the use of a larger supply voltage. Thick-oxide transistors have lower cut-off frequency F_t and lower gain performance at high frequency. So cascode configuration is a better choice to eliminate these two issues. But for cascode configuration amplifier, the supply voltage V_{DD} is twice, when compared with the single transistor amplifier. The dc power consumption will also be twice for the same current. This reduces the power efficiency of power amplifier.

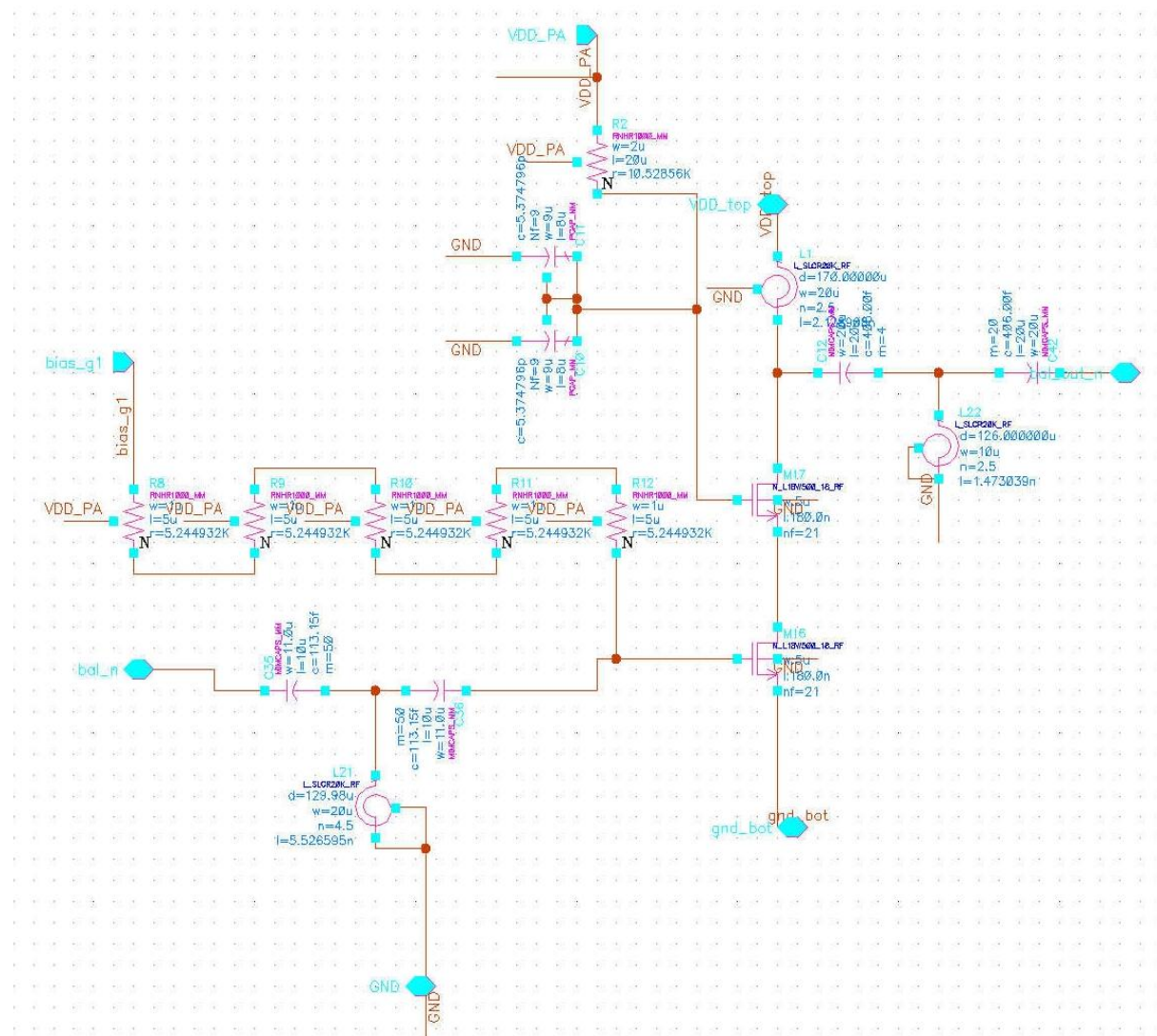


Figure 5. 13 Schematic of Single Ended Cascode Class A Power Amplifier

5.5.1 Circuit Operation

The Power Amplifier (PA) is the last stage of the transmitter chain. The PA amplifies the signal and delivers it to the antenna. The output power of an PA is 0 dBm. Figure

5.13 shows a single-ended Cascode PA with inductive load. The characteristics discussed for this single ended power amplifier are applicable to differential ones as well. The transistor M16 in Figure 5.13 converts the input voltage to current. The input voltage V_{in} is the modulated signal (at RF frequency) that will be transmitted. The gate oxides in standard CMOS processes have low break down voltages. The inductor L causes the V_{out} swing above and below V_{dd} voltage. If the transistor M17 was not present, increasing V_{out} voltage above V_{dd} could cause irreversible damages to M16. The transistor M17 not only protects M1 gate oxide, but also improves the reverse isolation of the PA.

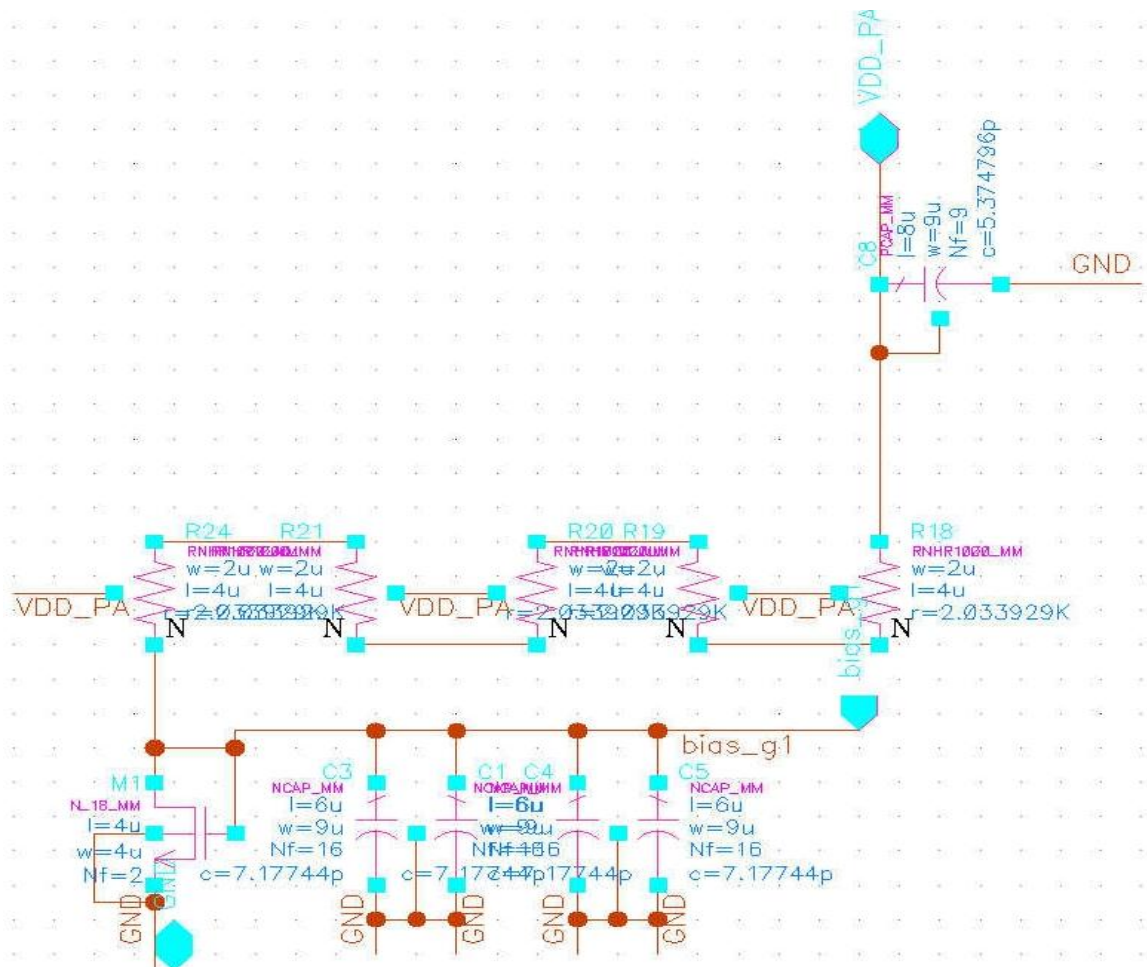


Figure 5. 14 Schematic of Biasing circuit for Class A Power Amplifier

Linear circuits involving transistor typically require specific DC voltages and currents to operate correctly, which can be achieved using a biasing circuit

Class A amplifier are considered to be the most linear since the transistor is biased in the centre of the load line to allow for maximum voltage and current swings without cut-off

saturation. For low distortion, the transistor is biased such that the output signal swing does not drive the transistor into a region of extremely nonlinear operation.

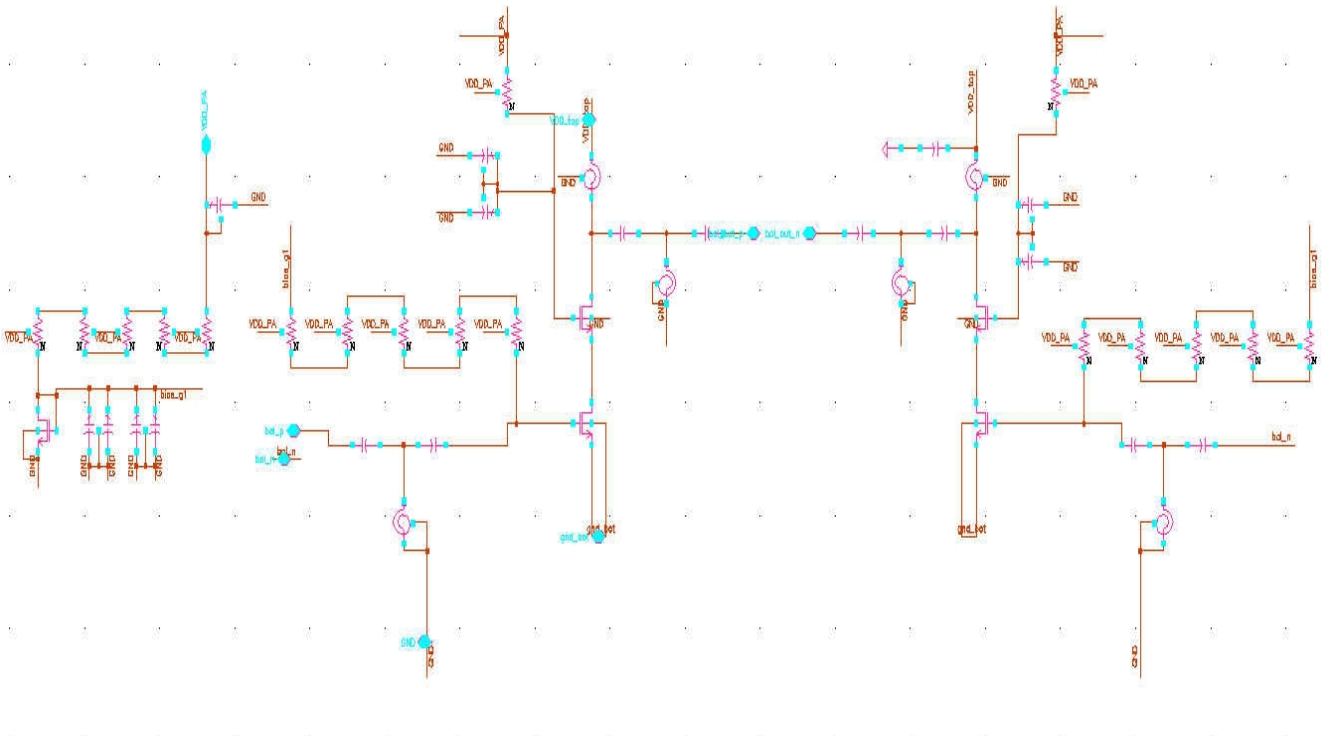


Figure 5. 15 Schematic of Differential Class A Power Amplifier

Integrated circuits usually employ differential topologies to avoid spurious injection from other blocks due to improved common-mode rejection, while it reduces even order harmonics. A fully differential configuration as shown in Figure 5.15 is used to alleviate the problem of substrate coupling. In a fully differential configuration, current is being discharged to ground twice per cycle. This expels the substrate noise component from the desired signal frequency to twice the signal frequency, resulting in a reduced interference. In addition, for the same supply voltage and output power, the current passing through each switch in a differential configuration is lower than its single-ended counterpart. This allows a smaller transistor to be used on each side without increasing the total switch loss. A differential configuration alone, however, might not provide sufficient relief to the transistor's input driving requirement, especially when large on/off driving signals are needed.

5.6 Results and Discussion

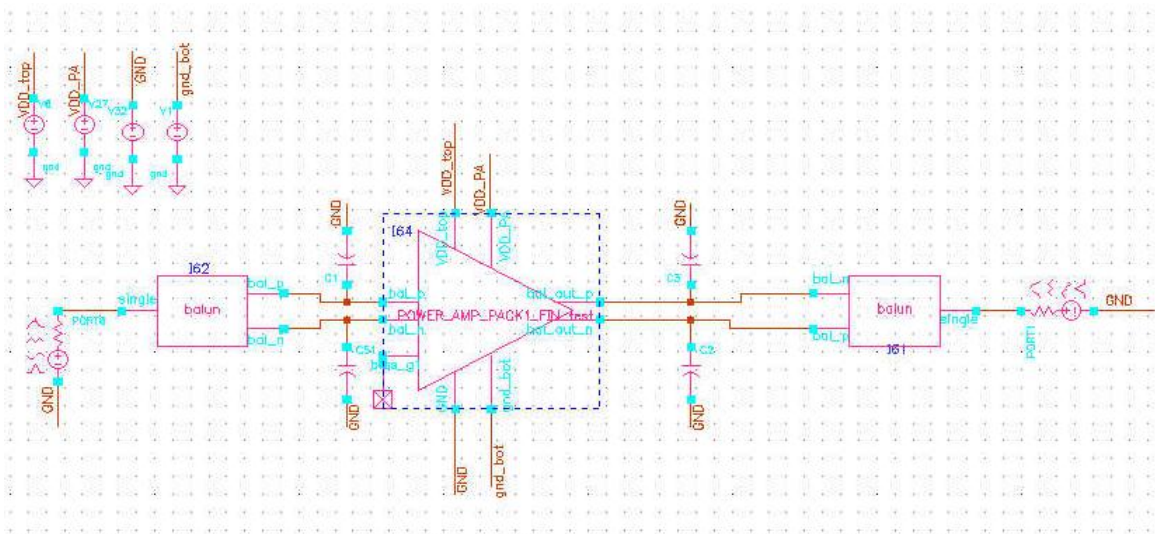


Figure 5. 16 Schematic of Differential Class A Power Amplifier Setup

Virtuoso® Analog Design Environment (2)

Status: Ready T=27 C Simulator: spectre 19

Session Setup Analyses Variables Outputs Simulation Results Tools Help

Design			Analyses			
Library	ZIGBEE_PA		#	Type	Arguments	Enable
Cell	TB_POWER_AMP_PACK1		1	sp	2G 3G 10M	Line yes
View	schematic		2	dc	t	yes
			3	tran	0 100n	yes

Design Variables			Outputs			
#	Name	Value	#	Name/Signal/Expr	Value	Plot Save March
1	freq1	2.45G	1	GT dB10	wave	yes
2	Prf	-10				
3	NF_CS	21				
4	NF_CG	21				

Plotting mode: Replace

> Results in ...lation/TB_POWER_AMP_PACK1_FIN_test_lay1/spectre/schematic

Figure 5. 17 Analog Design Environment of Differential Class A Power Amplifier Setup

The cascode Class A power amplifier operates at 2.4GHz by 1.8V supply voltage. The S parameters and power gain are simulated by Cadence© using SpectreRF simulator in UMC-0.18um Mixed Signal CMOS RF models. The input and output reflection coefficient, S11 and S22, are -1.558dB and -3.645dB, respectively. Power gain is 10dB at -10dBm input power level with the output power 0dBm. The PAE is 22%. DC power consumption is 4.5mW.

Power Amplifier that delivers 0dBm output power while consuming 2.5mA current from a 1.8V supply, has efficiency around 22%

$$\text{PAE} = \frac{\text{Output Power}}{\text{Input Power}} \times 100 = 22\%$$

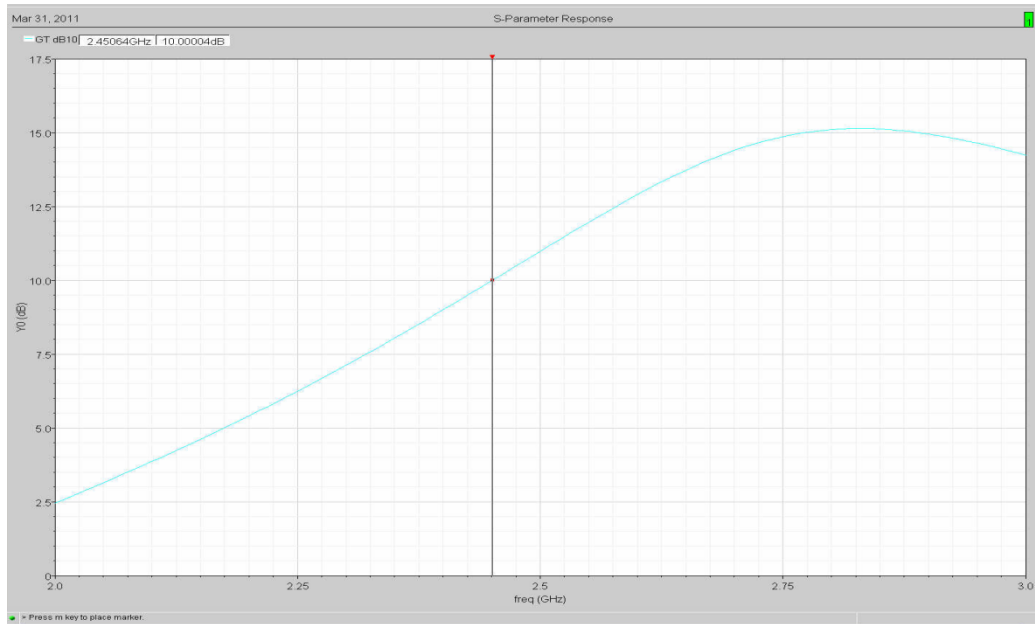


Figure 5.18 Transducer Power Gain of Differential Class A Power Amplifier

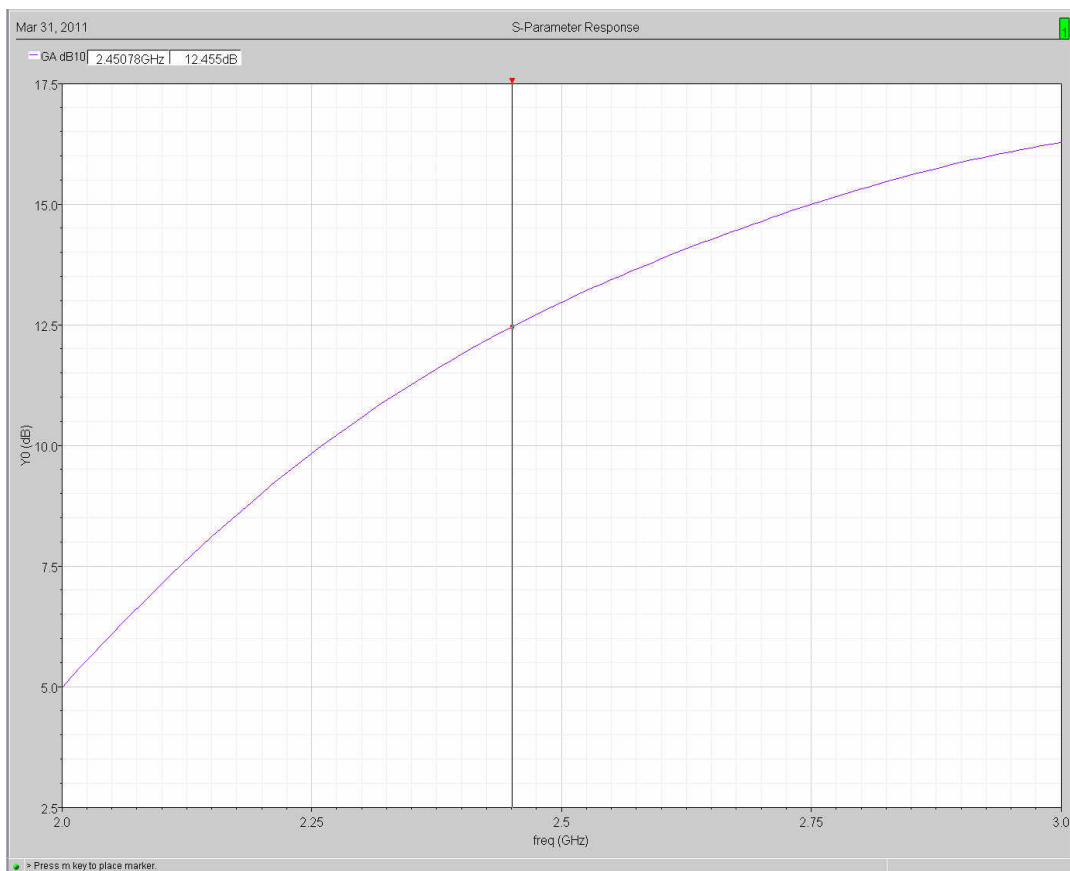


Figure 5.19 Available Power Gain of Differential Class A Power Amplifier

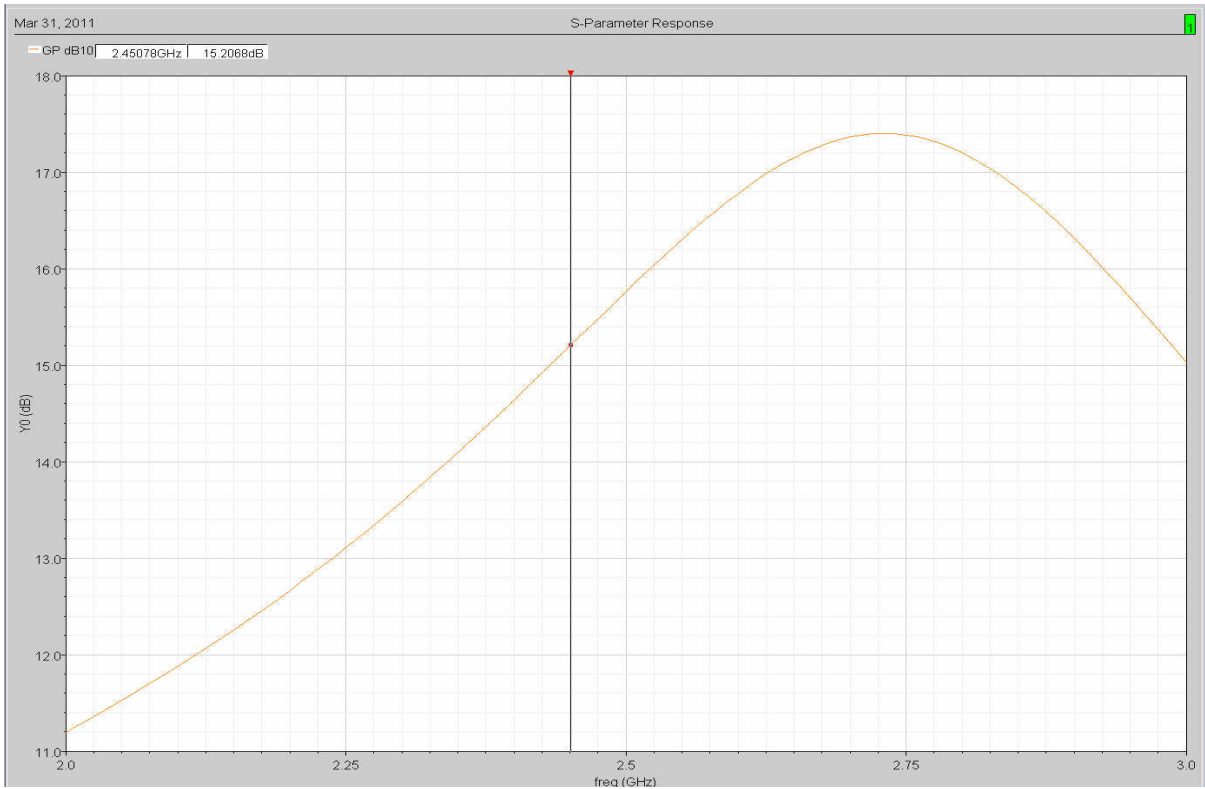


Figure 5. 20 Operating Power Gain of Differential Class A Power Amplifier

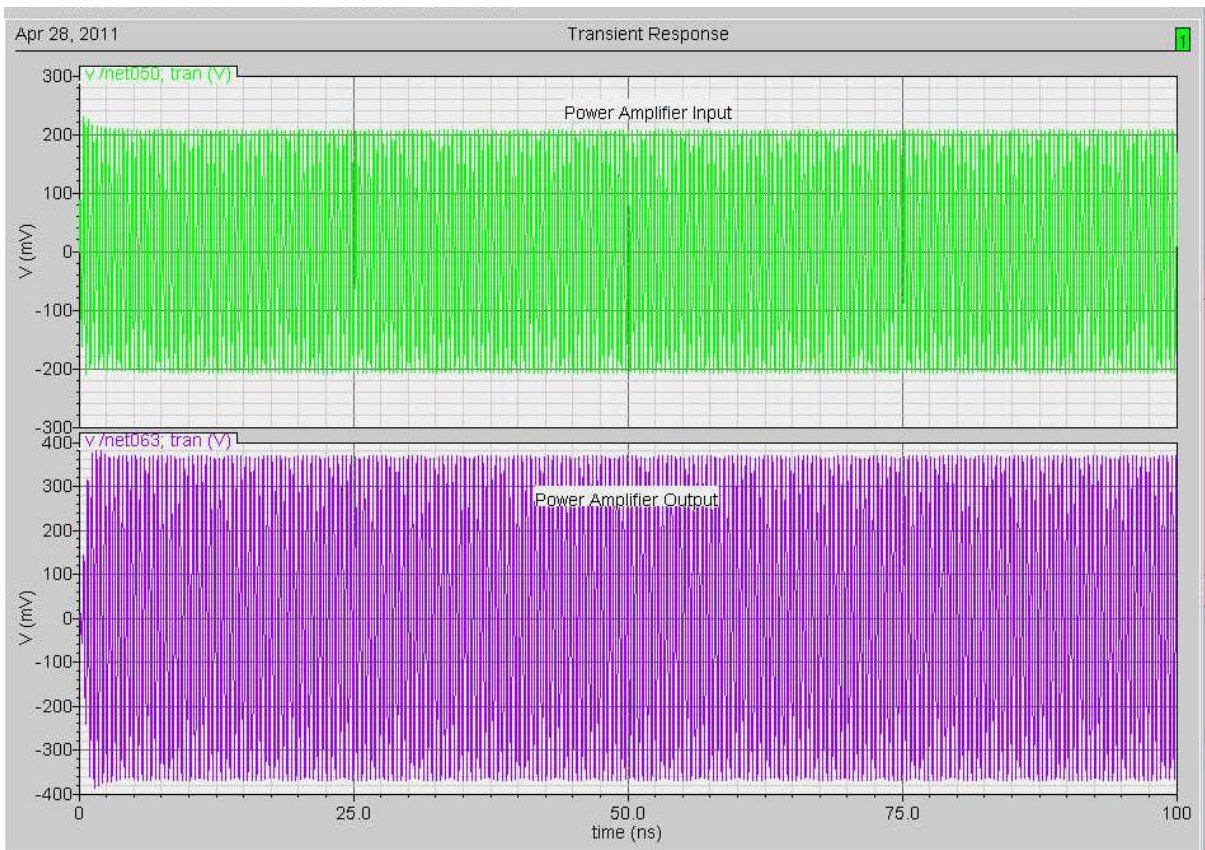


Figure 5. 21 Input and Output Transient Voltage of Differential Class A Power Amplifier

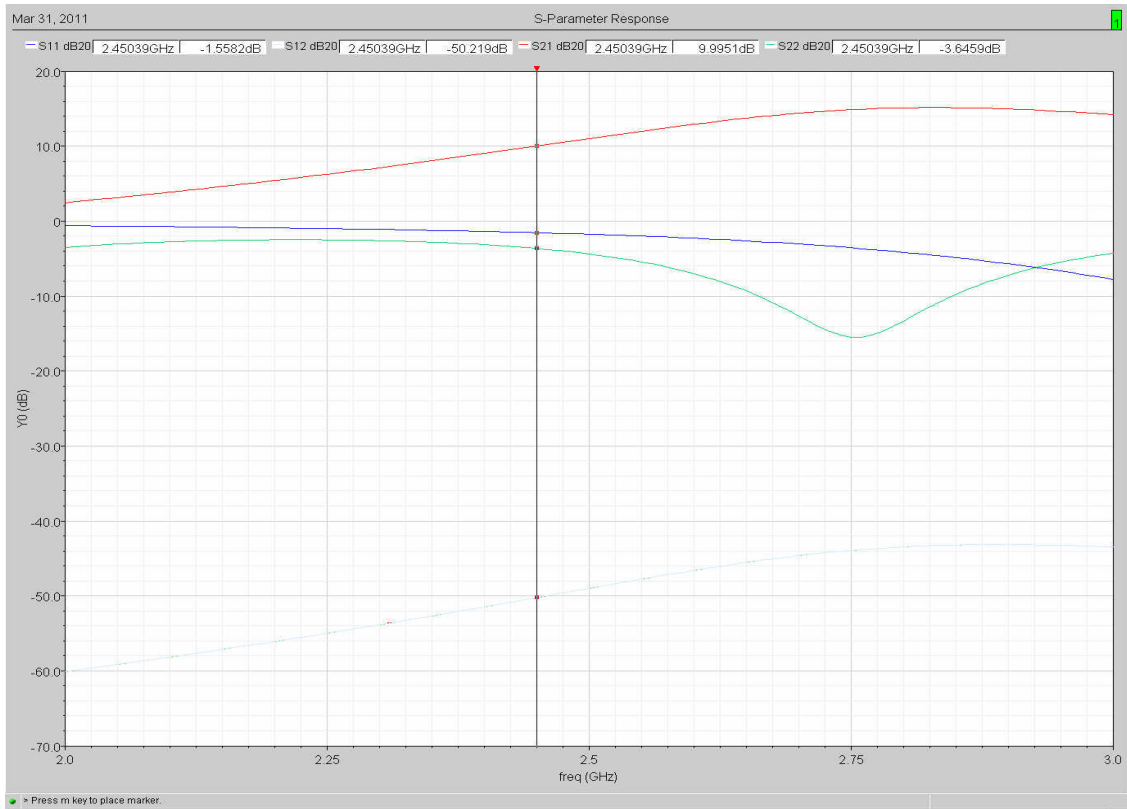


Figure 5. 22 S-Parameters of Differential Class A Power Amplifier

5.6.1 Layout Issues

In a differential topology, symmetry of on chip components and interconnect dimensions have a key role in the overall performance [24]. To achieve better matching, transistors are arranged in a symmetric, common-centroid structure along with dummy transistors so that current flows symmetrically from left to right. Special care has also been taken for resistor and capacitor matching. The failure mechanism for electrical overstress, such as electromigration and antenna effect are also considered for the layout. To sustain the large currents in different parts of the PA circuit, wide tracks and stacked metal layers are used. The transistors which have larger width. This demands the use of multifinger and folded transistors connected in parallel to reduce the resistance and obtain better current distribution. Different blocks are encapsulated with guard-rings to avoid cross-talk and decouple substrate noise. The layout of the differential amplifier is displayed in Figure. 5.23. The total chip area is (1202 μm x 1246 μm).

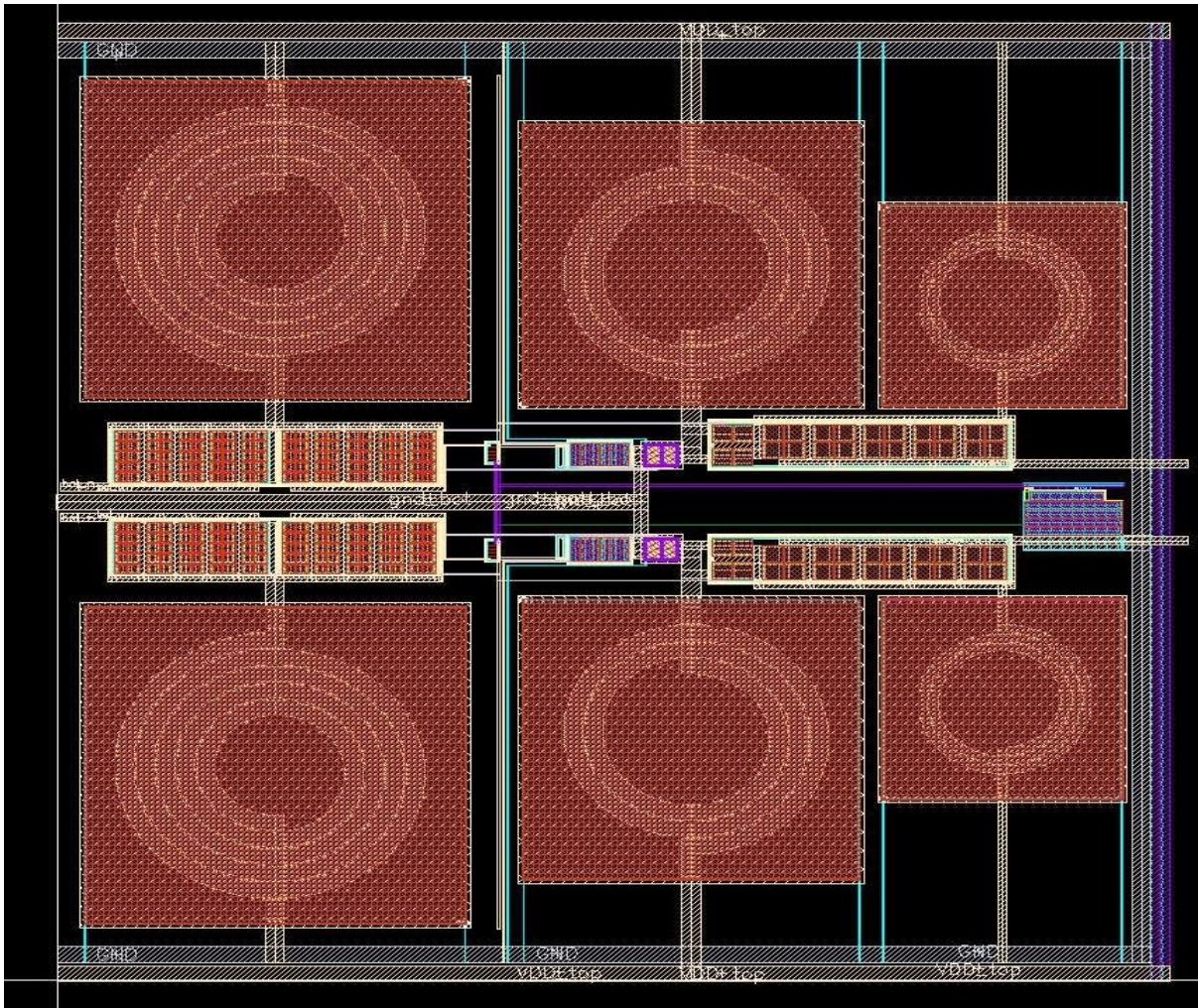


Figure 5. 23 Layout of Differential Class A power Amplifier

After creating Layout for Differential Class A Power Amplifier, we go for DRC to check all the process specific design rules have been met. Then we compare our layout with the schematic that we made earlier to see if they are both the same .Once the netlists matched we go for Post layout simulation. For performing Post layout simulation, an **analog_extracted** view for the Differential Class A Power Amplifier is required. So we generate a config window as shown in the Figure 5.24 and do the post layout simulation same as like schematic simulation

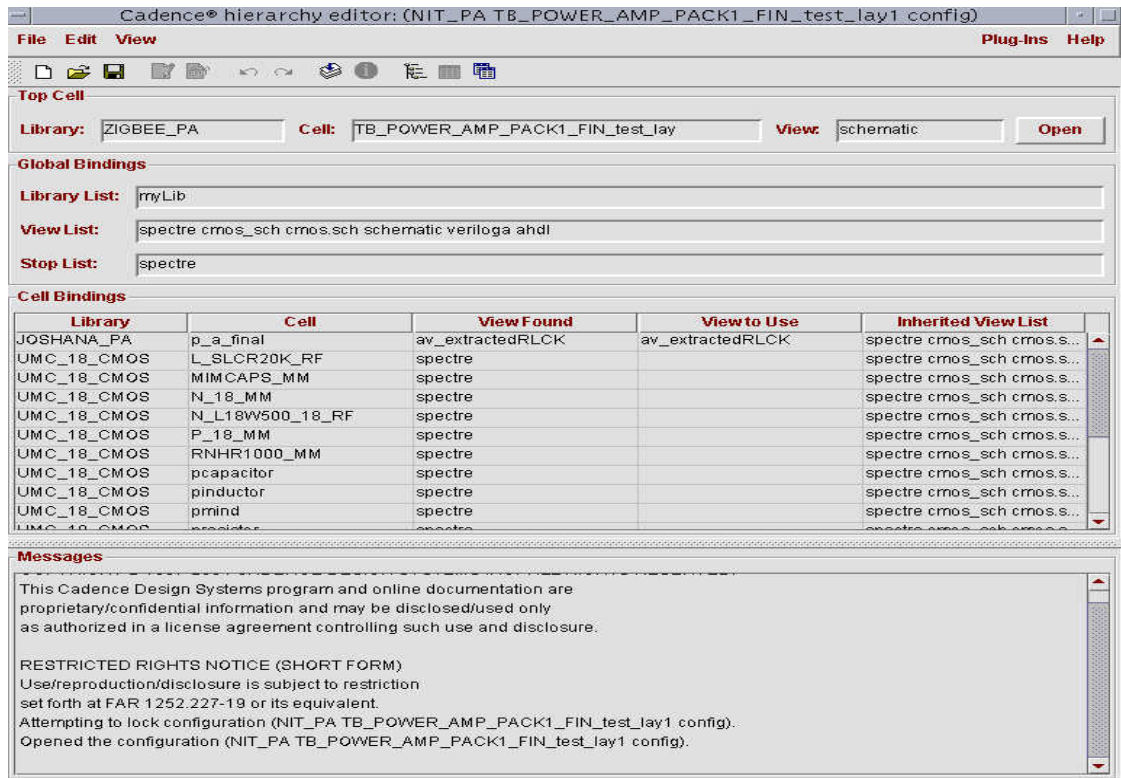


Figure 5. 24 Config Window of Differential Class A PA for Analog Extracted view

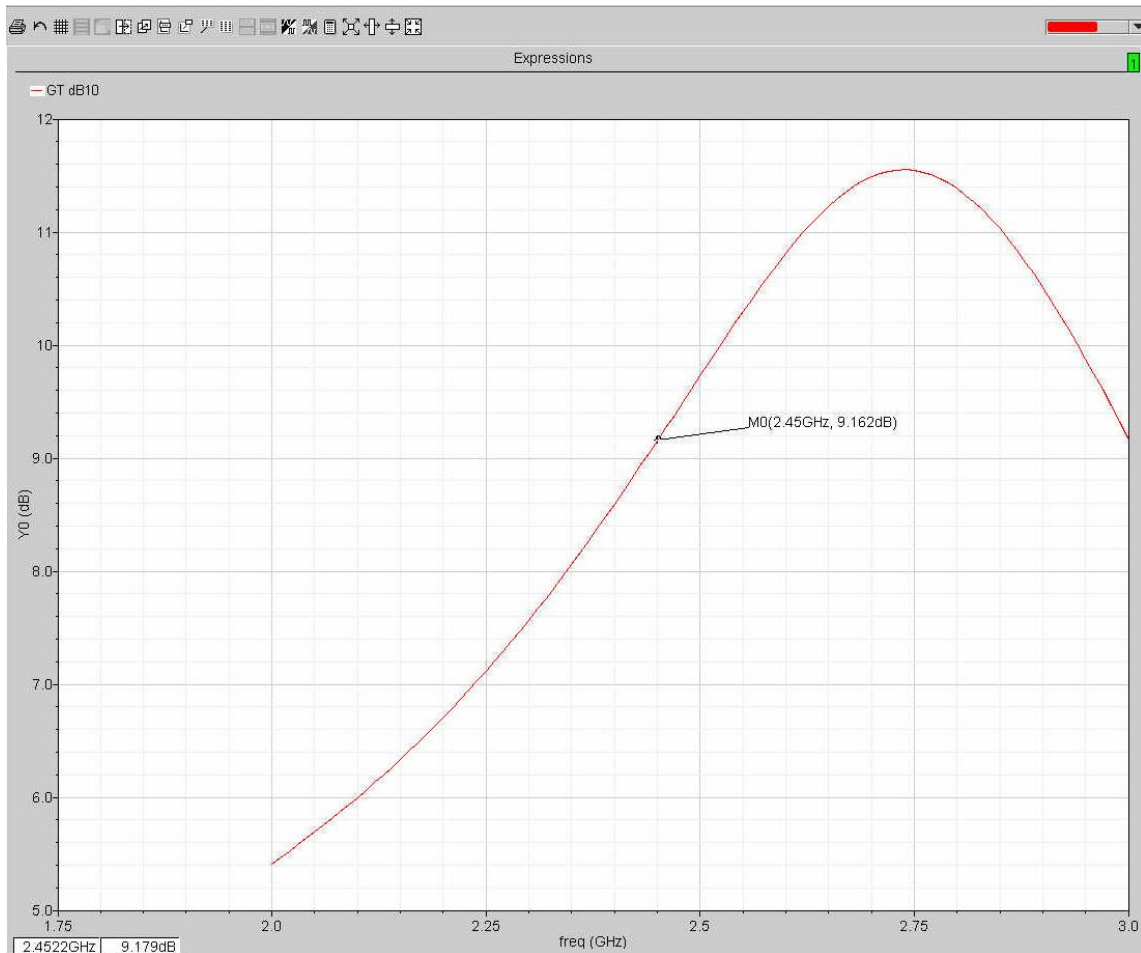


Figure 5. 25 Post-Layout simulation of Differential Class A Power Amplifier

The Post layout simulation for Differential Class A Power Amplifier as shown in the Figure 5.24 differs slightly from schematic simulation due to the influence of circuit parasitics such as parasitic capacitances and resistances

Table 5. 1 The Performance summary of Proposed Differential Class A Power Amplifier

S.No	Parameter	Values
1.	Operating frequency	2.45GHz
2.	Supply voltage	1.8V
3.	Current dissipation	2.5mA
4.	DC power dissipation	4.5mW
5.	Power added efficiency	22%
6.	Power Gain	10dB
7.	Technology	0.18um CMOS
8.	Technology Library	UMC

Chapter-6

Design of a Zigbee RF Transmitter

6.1 Design of a Zigbee Transmitter

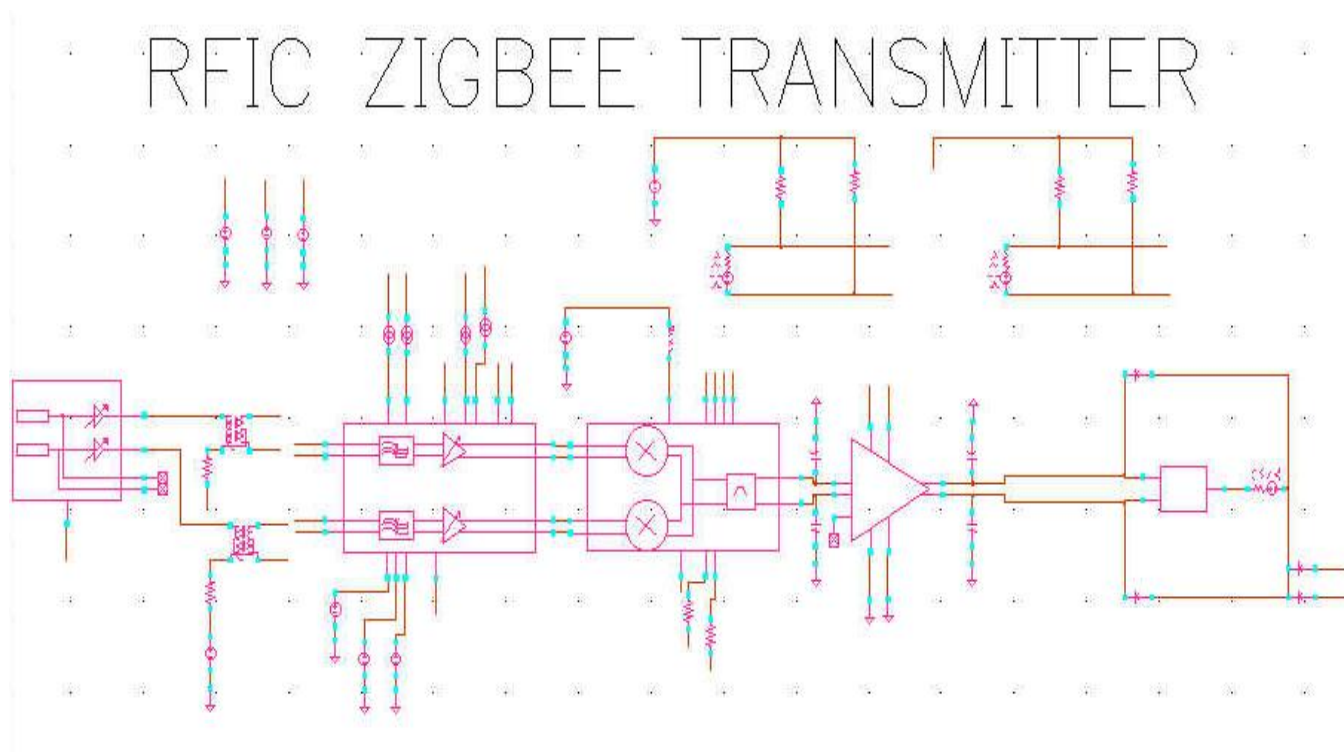


Figure 6. 1 Schematic of Zigbee Transmitter

A Schematic of Zigbee Transmitter is shown in the Figure 6.1. The schematic represents the integration of the various blocks which has been discussed in the previous Chapters. As we discussed earlier Zigbee Transmitter Comprises of Low Pass Filter, Variable Gain Amplifier, Up conversion Mixer and Power Amplifier. These blocks were integrated separately for In phase channel path and Quadrature phase channel path.

A random bit signal is generated by verilog program, this signal is given as an input to the Low Pass Filter which allows low frequency signal as its cut-off frequency is 5MHz. The Variable Gain Amplifier stabilizes the output of Low Pass Filter and provides a constant amplitude signal to the mixer. The mixer multiplies the incoming signal and the LO frequency signal of 2.45GHz, and passes through a prefilter which acts like a band pass filter, allowing the required band of frequency signal. This signal is given to the class A power amplifier which gives a better linearity and transfers maximum power to the load antenna of 50Ω ohms through the balun as shown in the Figure 6.1

6.2 Results and Discussion

The schematic of Zigbee Transmitter shown in the Figure 6.1 is simulated by Cadence® using SpectreRF simulator in UMC- 0.18um Mixed Signal CMOS RF models. Chosen Transient Analysis to observe the various transient voltages as shown in Figures 6.1, 6.2.

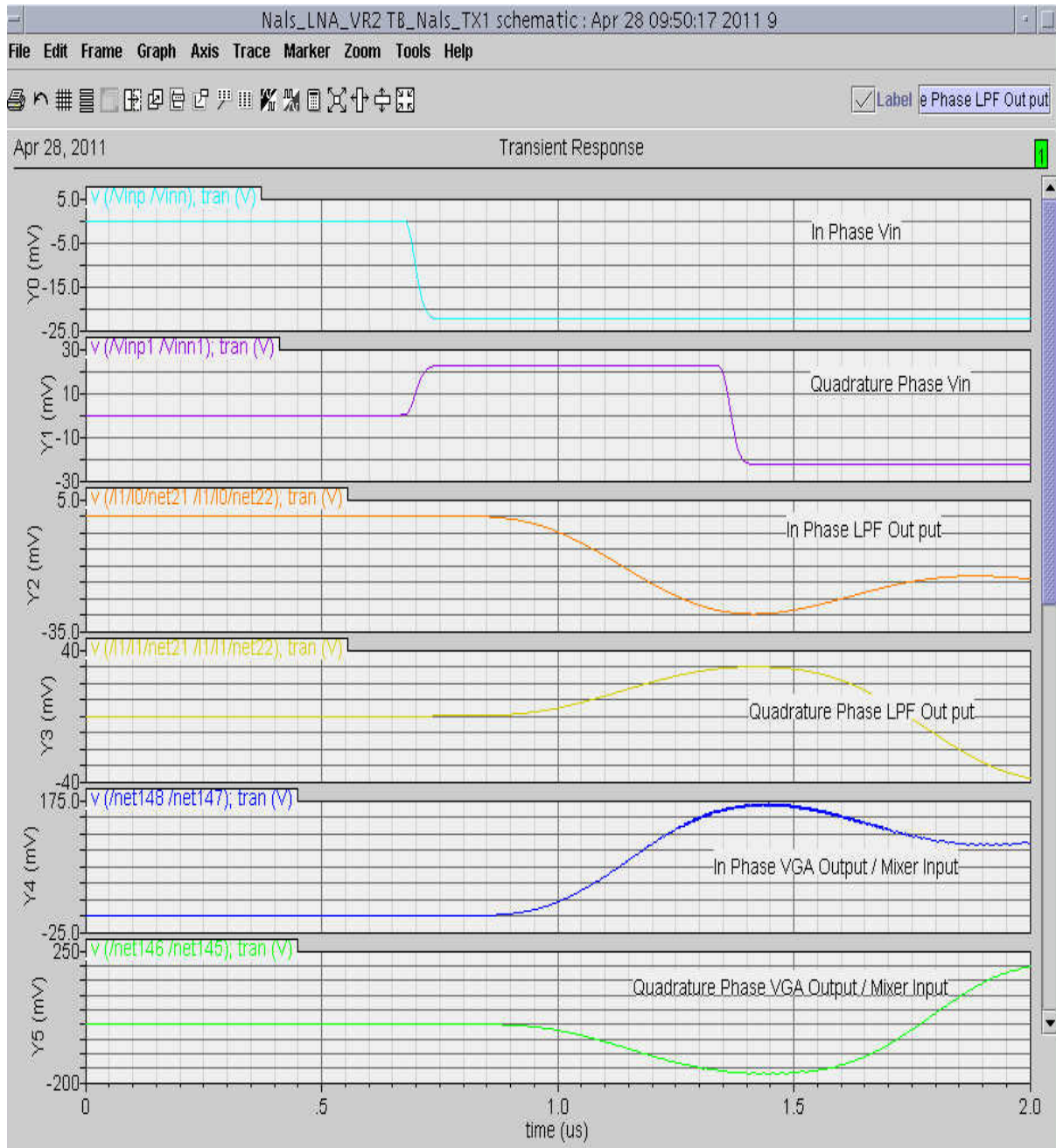


Figure 6. 2 Transient Voltage of In phase and Quadrature phase components of V_{in} , LPF output, VGA output/Mixer input.

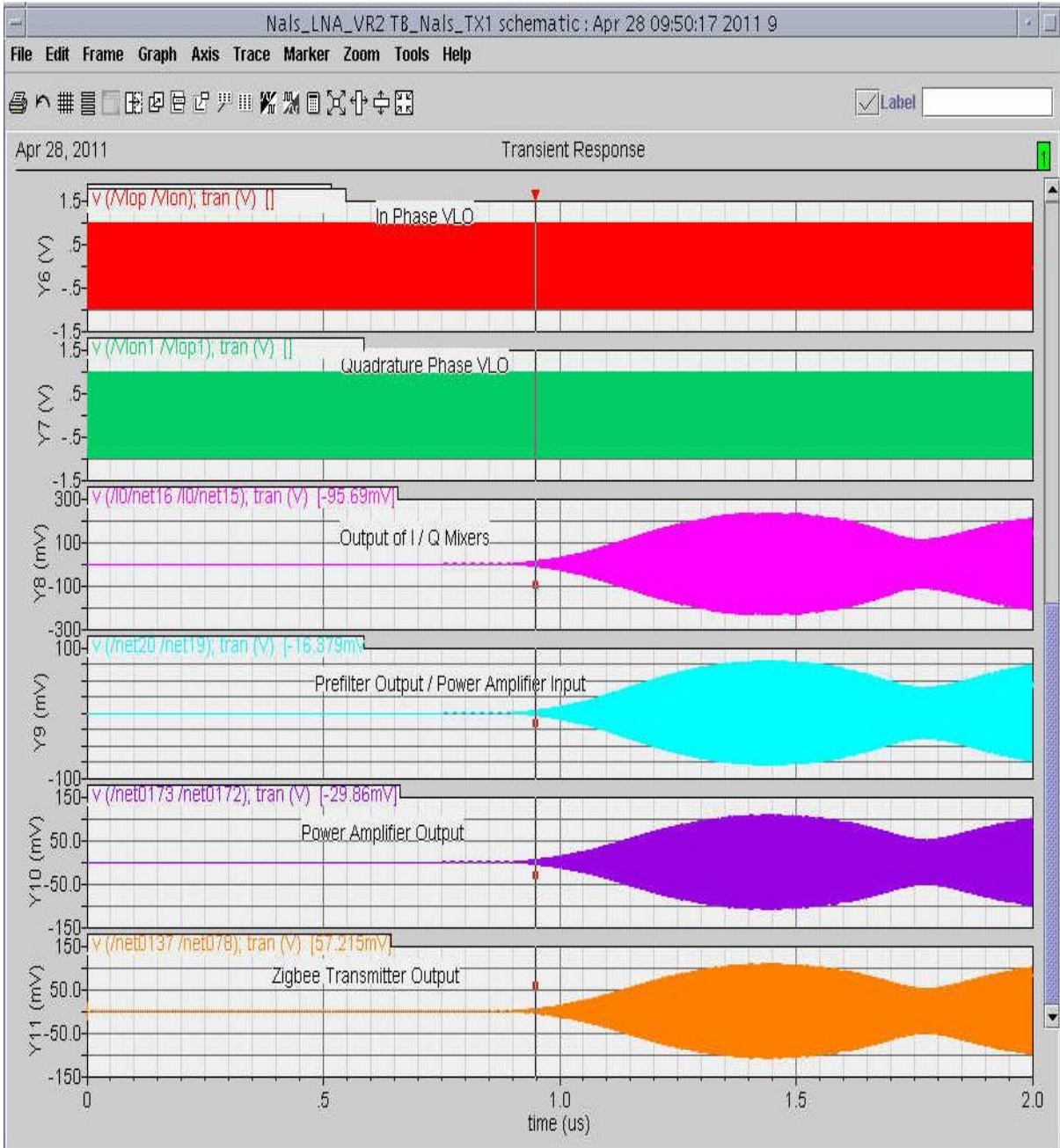


Figure 6. 3 Transient Voltage of In phase and Quadrature phase components of VLO, output of mixer, Power amplifier input, Power amplifier output and Zigbee Transmitter output

Chapter-7

Conclusion and Future Research

7.1 Conclusion

This Thesis has provided an analysis of radio frequency building blocks for a Zigbee Transmitter. In this work Zigbee Transmitter comprises of various blocks such as a Low Pass Filter, Variable Gain Amplifier, Up conversion Mixer, Power Amplifier. The Low Pass Filter allows the low frequencies and rejects all other unwanted high frequency signals.

The Variable Gain Amplifier has been discussed in Chapter 3 stabilises the output of the Low pass filter and provide constant amplitude to the various blocks. The gain variation is of 62dB (from 40 to -22).

The RF building blocks of transmitter are Up conversion Mixer and Power Amplifier which are discussed in Chapters 4, 5. The mixer performance is characterised and observed the excellent performance of high linearity which gives IIP3 35.26 dBm.

The Power hungry building block of RF transmitter is Power Amplifier. Here we designed a differential class A power amplifier to achieve linearity. The performance parameter are characterised and observed the Power Added Efficiency is 22% and Power gain is of 10dB.

And all these blocks were integrated and simulated using Cadence© SpectreRF simulator in UMC-0.18um Mixed Signal CMOS RF models for the best simulation results.

7.2 Future Research

Further future research work can be done on the temperature effects and noise performance on Variable Gain Amplifier, Up conversion Mixer and Power Amplifier of a Zigbee Transmitter for the best results.

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